

# RA2E1 Group

# **Examples of IO-Link Solutions**

# Introduction

This application note describes a sample application to realize IO-Link communication with RA2E1 using the Evaluation Kit for RA2E1 Microcontroller Group (EK-RA2E1), IA Sensor Network Connector Board, ZSSC3240 Evaluation Board, and EK-RA2E1 Change Board. IO-Link is a communication technology for sensors and actuators that complies with IEC61131-9. For IO-Link communication, the IO-Link stack manufactured by TMG is used.

## **Target Device**

• RA2E1, ZIOL2401 (IO-Link PHY), ZSSC3240

When applying this application note to other microcontrollers, modify any applicable configurations and settings according to the specifications of the microcontroller and evaluate any differences thoroughly.

# Contents

1.	Overview	3
2.	Confirmed operation environment	4
3.	Hardware Configuration	5
3.1	IO-Link Master	6
3.2	IA Sensor Network Connector Board (IO-Link Communication Board)	6
3.3	EK-RA2E1 Board	7
3.4	ZSSC3240 Evaluation Board	8
3.5	EK-RA2E1 Change Board	8
3.6	Power supply	9
3.6.1	Connect the 5V Service Power Supply	10
4.	Sample Application Overview	11
4.1	Overview of the Overall Processing Flow	12
4.2	Flowchart of App_SensorValue Function	14
4.3	Operating Mode and Switching State	19
4.4	IO-Link communication	20
4.4.1	Bit Rate	20
4.4.2	2 SIO Mode	20
4.4.3	B Process Data (PDIn)	
4.4.4	Parameters	21
4.5	Peripheral features and Terminals to be Used	22
4.6	Program Structure	24
4.6.1	File Structure	24
4.6.2	2 Function List	



# RA2E1 Group

5.	Sample Project Execution Method	.28
5.1	Importing Sample Projects	. 28
5.2	Build the Project	. 30
5.3	Setting up a Debug Connection between the EK-RA2E1 Board and the Host PC	. 32
5.4	Writing Sample Projects to the MCU	. 32
5.5	Start the Program	. 34
<u> </u>	10 Link Davies Teal Hears and Eurotians	25
6. 6.1	IO-Link Device Tool Usage and Functions IO-Link Device Tool V5.1 - Start PE	
6.2 6.3	Update IO-Link Device Catalog	
6.4	Update IO-Link Master Catalog	
	Check for Catalog Updates	
6.5 6.6	Setup for IO-Link communication	
	EK-RA2E1 Board Sensor Demo of IO-Link Device Tool	
6.6.1		
6.6.2		
6.6.3		
6.6.4		
6.6.5		
6.6.6	•	
6.6.7	5	
6.6.8	IODD Tab	. 54
7.	Examples of Use	55
7.1	Reset IO-Link parameters to default values	. 55
7.2	Operating Methods	. 55
8.	How to Change ZSSC Settings	.59
8.1	USB-SERIAL Conversion Cable Connection	
8.2	Check the Virtual COM Port Number	
8.3	Start the ZSSC GUI	. 62
8.4	Establish a Communication Path	
8.4.1	Open Port	. 63
8.4.2	Interface	. 64
8.4.3	Scan I2C-Bus	. 65
8.5	Measurement (Corr. Measurement)	
8.6	NVM Operation	. 71
8.6.1	Read NVM	. 71
8.6.2	Write NVM	. 73
8.6.3	Write CRC	. 74
8.6.4	Return ADC resolution set value	. 75
9.	References	75



<b>Revision History</b>	77	76
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# 1. Overview

This application note describes how to realize IO-Link communication using IO-Link stack manufactured by TMG.

In this example, EK-RA2E1 board and IA Sensor Network Connector Board are used as IO-Link devices, and IO-Link-Master02-USB manufactured by Pepperl + Fuchs is used as IO-Link master. For communication with the IO-Link master, "IO-Link Device Tool V5.1 - PE" provided by TMG is used. "IO-Link Device Tool V5.1 - PE" is an application software that runs on a Windows PC.

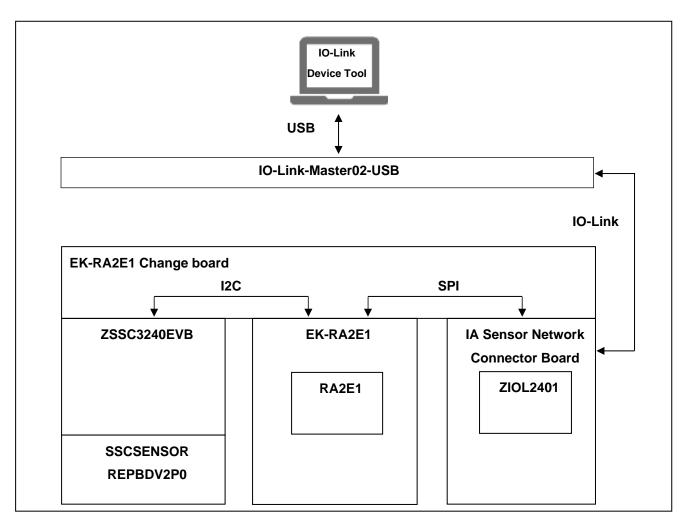


Figure 1. System Configuration in this Application Note



# 2. Confirmed operation environment

The confirmed operation environment is shown in Table 1. The configuration of the device is described in section 3 Hardware .

#### Table 1. Development Environment

Item	Description
CPU board	EK-RA2E1 board
MCU	R7FA2E1A92DFM
IDE	Renesas e <sup>2</sup> studio 2022-04 (22.4.0)
Tool Chain	GCC ARM Embedded 10.3.1.20210824
FSP	3.7.0
Library	IO-Link stack manufactured by TMG
Emulator	SEGGER J-Link OB
IO-Link communication board	IA Sensor Network Connector Board (RTK0EF0085B00001BJ)
	It is connected to the EK-RA2E1 board and operates as an IO-Link
	device.
IO-Link Line Driver	ZIOL2401
IO-Link Master	PepperI+Fuchs IO-Link-Master02-USB
	Device Type Manager <sup>1</sup>
IO-Link Tool	IO-Link Device Tool V5.1 – PE
Host PC for IO-Link Tool	Windows10 Professional
ZSSC3240EVK	ZSSC3240 Evaluation Kit
ZSSC3240EVB	SSC evaluation board with ZSSC3240
SSCCOMMBOARDV4P1C	CB (SSC communication board)
	CB H/W Version (SSC CB V4.1)
	CB F/W Version (V4.19 © ZMD AG 2020 – CB    SVN: 11903)
	* This board is included in the ZSSC3240EVK, but is not used in this
	application. The EK-RA2E1 board is the pipe for communication
	between the PC and the ZSSC3240EVB.
SSCSENSORREPBDV2P0	SRB (Sensor Replacement Board)
ZSSC GUI	ZSSC3240 Evaluation Software (manual COMport selection,
	recommended for older PC) v3.02
EK Change Board	It connects EK-RA2E1, ZSSC 3240EVB, and IA Sensor Network
EX-EK-RA2E1	Connector Board.
USB-SERIAL conversion cable	FT232RL built-in USB-SERIAL conversion cable

Note<sup>1</sup>: If IO-Link-Master02-USB is not detected in the IO-Link Device Tool master search (section 6.5), reinstall the software "Device Type Manager".



# 3. Hardware Configuration

This application uses the IO-Link master and IO-Link device. IO-Link master is composed of Pepperl+Fuchs IO-Link-Master02-USB, and IO-Link device is composed of ZSSC3240 Evaluation Board, EK-RA2E1 Board, IA Sensor Network Connector Board and EK-RA2E1 Change Board to connect them. The connection of each board is shown below.

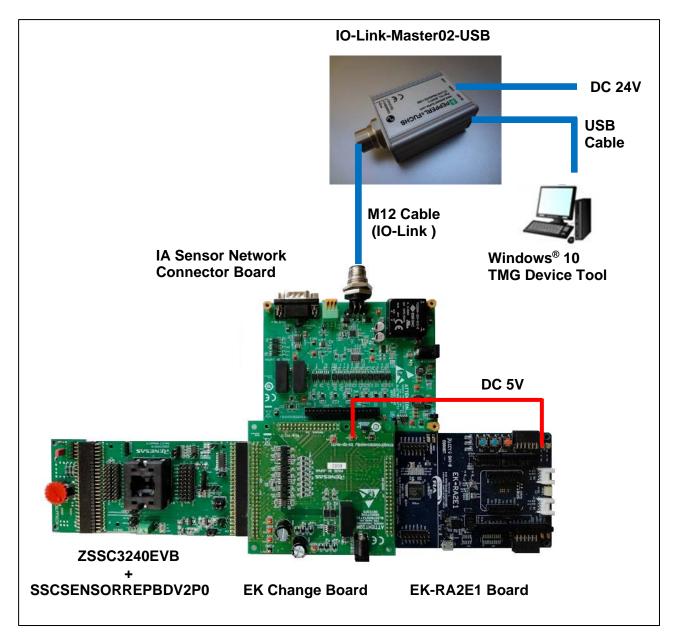


Figure 2. Hardware Configuration



# 3.1 IO-Link Master

In this application note, Pepperl+Fuchs IO-Link-Master02-USB is used.



Figure 3. I-O Link Master Connector Description

Connect DC 24V to DC jack for power supply, and the USB cable to the USB terminal.

Connect IO-Link cable M12 to the connector.

# 3.2 IA Sensor Network Connector Board (IO-Link Communication Board)

This board supports "IO-Link", "RS485" and "CAN", but only "IO-Link" will be used in this application note.

Power is supplied from the IO-Link master board through the IO-Link cable.

Jumper is set to JP1: 1-2 and JP2: Open.



Figure 4. IO Link Communication Board

Note: Connecting the M12 cable to the IO-Link communication board while power is supplied to the IO-Link master may damage the IO-Link communication board. M12 cable connection to the IO-Link communication board should be made with no power supplied to the IO-Link master.



# 3.3 EK-RA2E1 Board

Write the sample project firmware to this board to control the measurement with ZSSC and IO-Link communication with the IO-Link master.

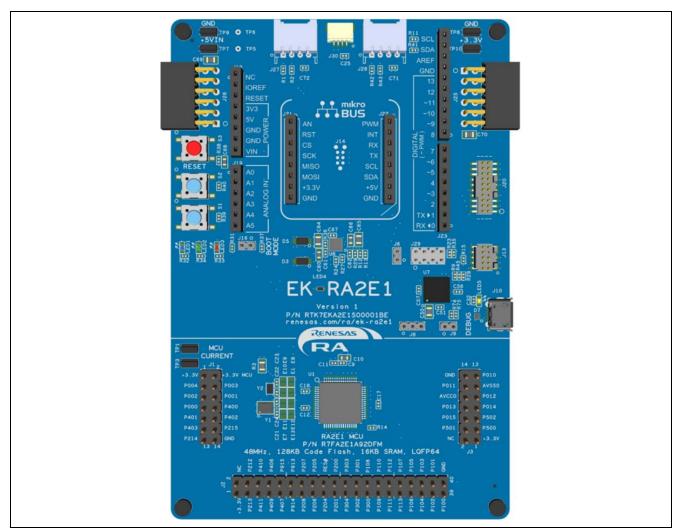


Figure 5. EK-RA2E1 Board



# 3.4 ZSSC3240 Evaluation Board

The ZSSC3240 Evaluation Board (hereafter referred to as "ZSSC EVB") and the Sensor Replacement board (hereafter referred to as SRB) are used. There are three types of communication methods, I2C, SPI, and OWI, but in this application note, only I2C is covered.

To use the ZSSC EVB with I2C, connect 1-2 of J21/J22 to the jumper on the board.

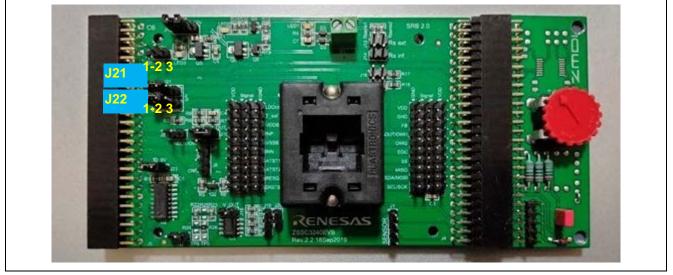


Figure 6. ZSSC3240 Evaluation Board (I2C Setting)

# 3.5 EK-RA2E1 Change Board

This conversion board is used to connect [ZSSC3240 Evaluation Board] [EK-RA2E1 Board] [IA Sensor Network Connector Board].

The power is supplied from the IO-Link communication board through the I/F connector, and the ZSSC EVB is also powered from this board. The EK-RA2E1 board can also be powered by connecting the 5V service output of this board to the + 5VIN terminal of the EK-RA2E1 board by cable.

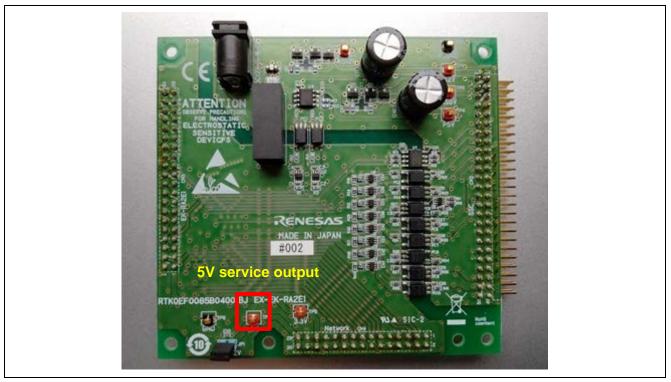


Figure 7. EK-RA2E1 Change Board



# 3.6 Power supply

The power supply to each board is supplied from the IO-Link-Master02-USB through the IO-Link M12 Cable.

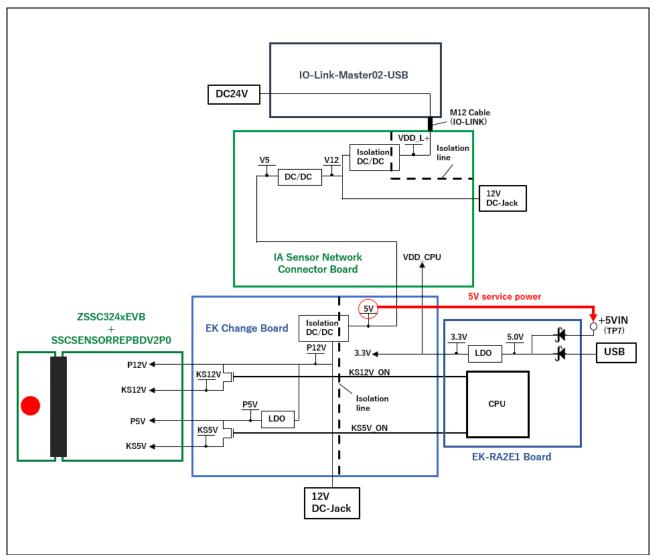


Figure 8. Power Supply



# 3.6.1 Connect the 5V Service Power Supply

Connect 5V(TP7) on the conversion board to +5VIN(TP7) on the EK-RA2E1 Board to supply power to the EK-RA2E1 Board.

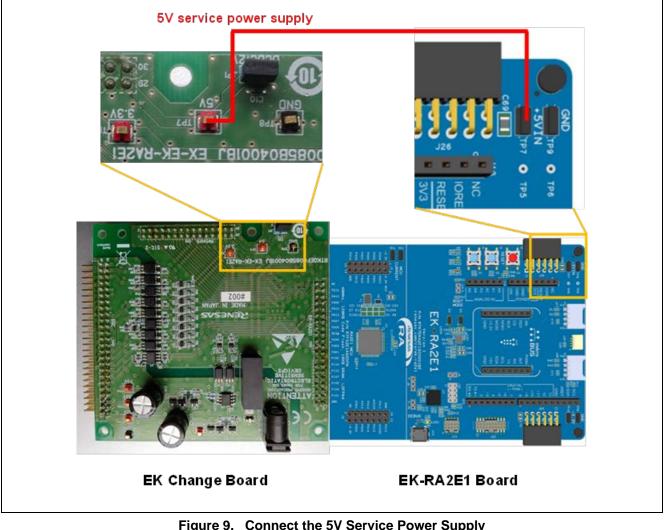


Figure 9. Connect the 5V Service Power Supply



# 4. Sample Application Overview

The IO-Link device used in this sample application is equipped with a smart sensor profile and receives information about switching modes and thresholds through a teaching process. The IO-Link device executes the measurement and threshold judgment periodically (once every 100 ms) and sends the information to the master via IO-Link communication. The information to be sent (process data) consists of measurement values and switching states (threshold judgment results).

For more information on the smart sensor profile, please refer to the documentation related to the IO-Link smart sensor profile, which can be downloaded from <a href="https://io-link.com/en/">https://io-link.com/en/</a>.

This is an overview of the software components that make up the sample application.

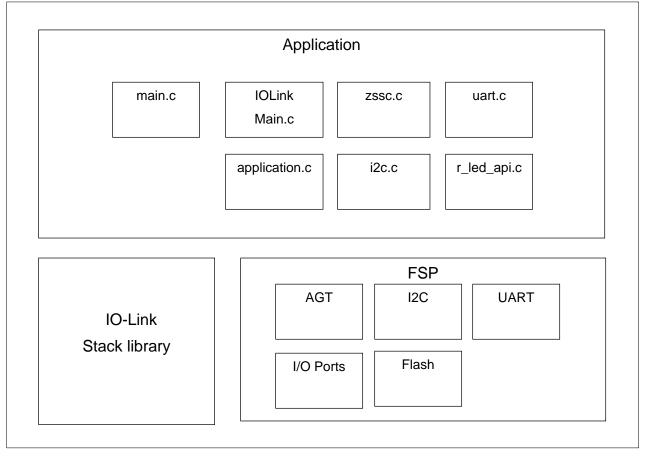


Figure 10. Software Components



### 4.1 Overview of the Overall Processing Flow

The processing flow of the sample application is described.

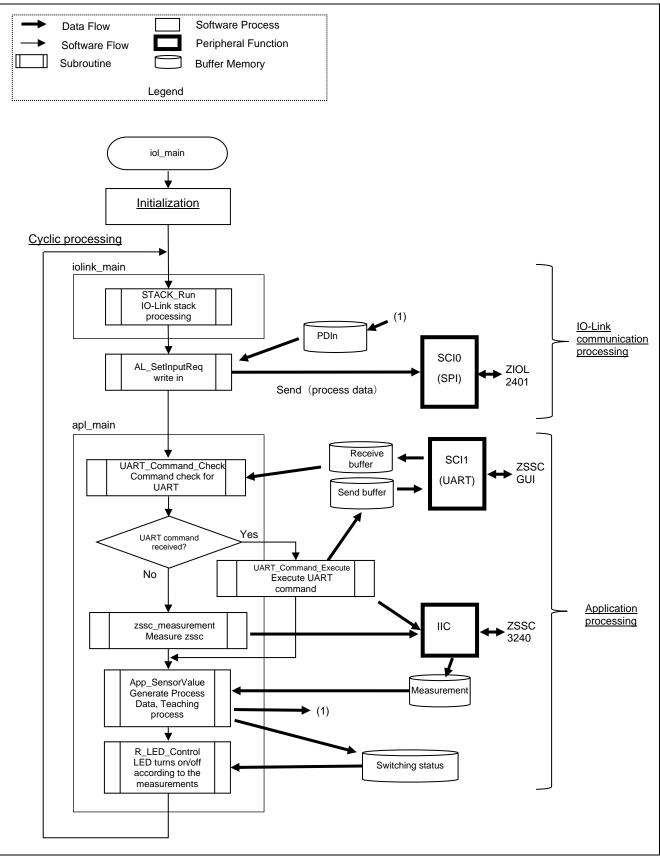


Figure 11. Processing Flow of the Sample Application



The outline of each process is described as follows:

- 1. Initialization Initializes IO-Link, UART, I2C, and resets ZSSC. It also reads ZSSC NVM data and stores it in a variable.
- 2. IO-Link communication processing
  - A. Run STACK\_Run (iolink\_main) Execute STACK\_Run, which is the API provided by the IO-Link stack.
  - B. Process data writing process Execute AL\_SetInputReq, which is the API provided by the IO-Link stack. Pass a pointer to the process data as an argument.
- 3. Application processing
  - A. Execution of UART command reception check function (UART\_Command\_Check) Check UART command reception.
  - B. State transition depending on whether UART commands are received If a command is received, the UART\_Command\_Execute function is executed to process the UART command.
     If the UART command is an NVM setting command, the NVM data is read and stored in a variable.
  - C. Measurement processing

If UART command is not received, zssc\_measurement is called and ZSSC measurement is executed. If a measurement command has been received from ZSSC GUI, it issues a measurement command in UART\_Commnad\_Execute and executes the measurement. In either case, the measurement result is stored in a global variable (measurement).

D. Generate Process Data, Teaching process (App\_SensorValue)

Generates process data from the measurements. If the Teaching command is being executed, a parameter check is performed, and if it is outside the valid range, the Teaching command fails. If it is within the valid range, the Teaching command

succeeds and the SP1 or SP2 setting value is updated according to the command. The switching state is judged based on the operation mode and the measurements. when the

Teaching command is being executed (Teach\_Result is other than IDLE or SUCCESS), the switching state is not judged and the switching state is OFF.

If ConfigLogic (logical setting of the switching state) is set to Inverted, the switching state bit is inverted.

For details of this process, refer to section, 4.2 Flowchart of App\_SensorValue Function.

- E. LED on/off (R\_LED\_Control) Pass the switching status to the argument of R\_LED\_Control. If the switching status is ON, the LED is turned on; if OFF, the LED is turned off.
- 4. Cyclic processing

Return to step 2 and repeat the cyclic processing.



# 4.2 Flowchart of App\_SensorValue Function

The flowchart of the App\_SensorValue function is shown in Figure 12.

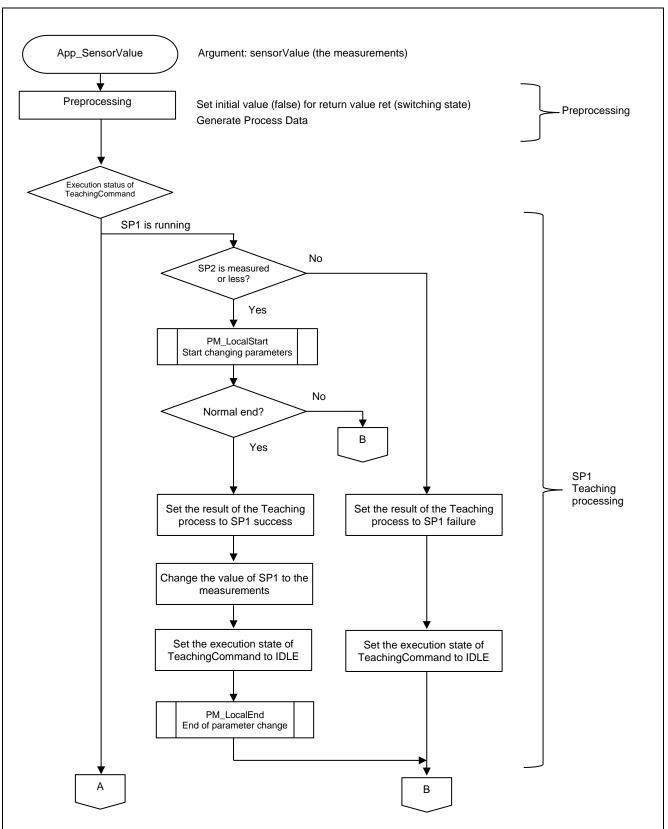


Figure 12. App\_SensorValue Flowchart (1/4)



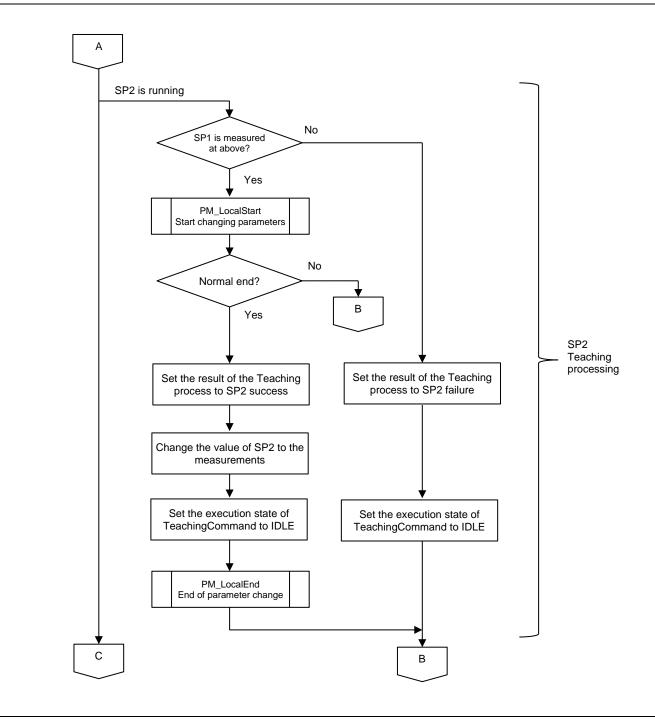


Figure 13. App\_SensorValue Flowchart (2/4)



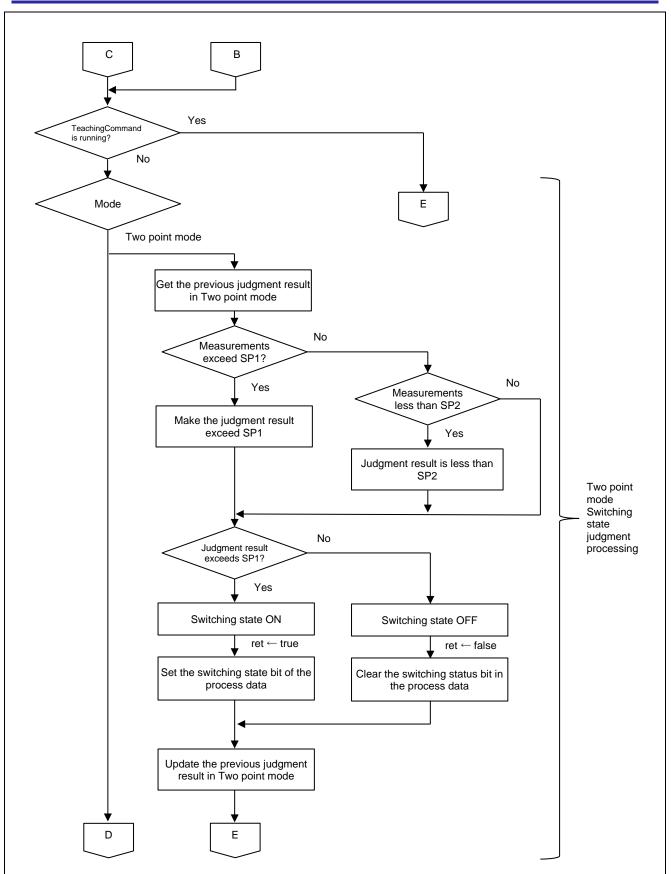


Figure 14. App\_SensorValue Flowchart (3/4)



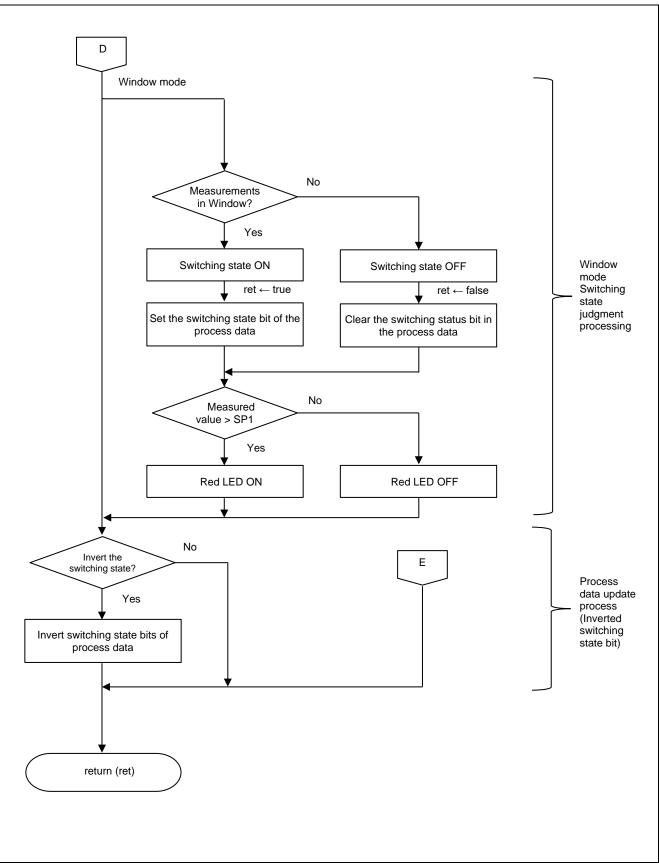


Figure 15. App\_SensorValue Flowchart (4/4)



The outline of each process is described as follows:

- 1. Preprocessing
  - Set the initial value (false: OFF) to the return value ret (switching state).
  - Generate Process Data.
  - Stores the lower 24 bits of the sensor value (32 bits) passed in the argument in ProcessData.
  - Stores the sensor value [16:23] bit in ProcessData.PDIn[1].
  - Stores the sensor value [8:15] bit in ProcessData.PDIn[2].
  - Stores the sensor value [0:7] bit in ProcessData.PDIn[3].
  - Stores the Switching Point1 detection status in the least significant bit of ProcessData.PDIn[5].
- 2. SP1 Teaching processing<sup>\*note</sup>

When the execution status of TeachingCommand is "TeachingCommand of SP1", the following process is performed.

- Since SP1 ≥ SP2 must be satisfied, the result of the Teaching process (ParSetStatic.V\_TeachResult) is set as SP1 failure when the measurements < SP2.</p>
- In other case, the result of Teaching process is set as SP1 success, the measurements are copied to SP1 (ParSet.V\_SetPointValues.SP1), and the execution status of TeachingCommand is set to idle.
- 3. SP2 Teaching processing \*note

When the execution status of TeachingCommand is "TeachingCommand of SP2", the following process is performed.

- Since SP1≥SP2 must be satisfied, the result of the Teaching process (ParSetStatic.V\_TeachResult) is set as SP2 failure when SP1 < the measurements.</p>
- In other case, the result of Teaching process is set as SP2 success, the measurements are copied to SP2 (ParSet.V\_SetPointValues.SP2), and the execution status of TeachingCommand is set to idle.
- 4. Two point mode Switching state judgment processing

When TeachingCommand is not running (idle or success) and the operation mode

(ParSet.V\_SetPointConfig.Mode) is Two point mode, the following process is performed.

- Get the previous judgment result of Two point mode (initial value is less than SP2).
- If SP1< measurements, the judgment result is SP1 exceeded.
- If SP2> measurements, the judgment result is less than SP2.
- In other cases, the judgment result is the previous judgment result.
- If the judgment result exceeds SP1, the switching state is set to ON and ProcessData.PDIn[5] is set to 1.
- If the judgment result is less than SP2, the switching state is set to OFF and ProcessData.PDIn[5] is set to 0.
- Update the previous judgment result in the Two point mode to the current judgment result.
- 5. Window mode Switching state judgment processing

When TeachingCommand is not running (idle state or success) and the operation mode

(ParSet.V\_SetPointConfig.Mode) is Window mode, the following process is performed.

- If SP1≥measurements ≥SP2, the switching state is set to ON and ProcessData.PDIn[5] is set to 1.
- In other cases, the switching state is set to OFF and ProcessData.PDIn[5] is set to 0.

Red LED processing:

- If SP1 < current sensor value, the red LED turns on.
- If SP1  $\geq$  current sensor value, the red LED turns off.
- 6. Process data update process (Inverted switching state bit)

When the switching state logic setting (ParSet.V\_SetPointConfig.Logic) is 1 (Inverted), the following process is performed.

Invert the least significant bit of ProcessData.PDIn[5].



Note: When changing ParSet.V\_SetPointValues, execute the PM\_LocalStart function provided by the IO-Link stack, make sure that the return value is True, and then make the change. After the change, it is necessary to execute the PM\_LocalEnd function. If the return value of the PM\_LocalStart function is false, exit the App\_SensorValue function without changing the execution status of ParSetStatic.V\_TeachResult, Parset.V\_SetPointValues, and TeachingCommand, and retry the Teaching process in the next post-measurement process.

# 4.3 Operating Mode and Switching State

The operation mode and switching state of this sample application are described. In order to check the switching status by LED as well as process data, the LED is turned on and off according to the switching status.

• Window mode

When Switching Point1(SP1)  $\geq$  measurements  $\geq$  Switching Point2 (SP2) is met, the LED(green) turns ON.

When measurements > Switching Point1(SP1) is met, LED (red) turns on when the measured value is satisfied.

• Two point mode

In this mode, the switching state is determined with hysteresis.

- If the measured value is rising, the threshold is at Switching Point 1 (SP1). Once the measured value
   SP1 is met, the LED (green) changes to ON. After that, the state is maintained until the measured value falls below SP2.
- If the measured value is falling, the threshold is at Switching Point 2 (SP2). Once SP2 > measured value is met, the LED (green) changes to OFF. After that, the state is maintained until the measured value exceeds SP1.

The operation image is described.

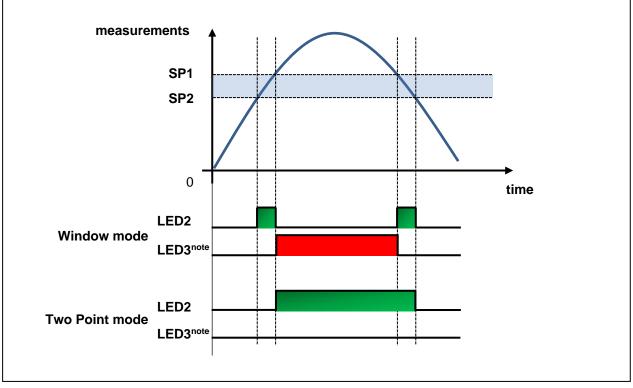


Figure 16. LED Operation Image

Note: The red LED works only in Window mode. Also, the status of the red LED is not reflected in Process Data, so you cannot check the status with the TMG Device Tool.



### 4.4 IO-Link communication

IO-Link communication specifications are described.

#### 4.4.1 Bit Rate

The bit rate is COM2 (38.4 kbps).

#### 4.4.2 SIO Mode

SIO mode is not supported in this sample application.

#### 4.4.3 Process Data (PDIn)

The measurement information is sent to the IO-Link master as process data. The contents of the process data are described in Table 2.

Process Data (PDIn)		Data leng	gth : 6 bytes
PDIn[n]	Bit	Stored data	Details
PDIn[0]	0-7	Sensor Value(bit24-32)	Stores Bit [24-32] of the sensor value
PDIn[1]	0-7	Sensor Value(bit16-23)	Stores Bit [16-23] of the sensor value
PDIn[2]	0-7	Sensor Value(bit8-15)	Stores Bit [8-15] of the sensor value
PDIn[3]	0-7	Sensor Value(bit0-7)	Stores Bit [0-7] of the sensor value
PDIn[4]	0-7	-	(Not used)
PDIn[5]	1-6	-	(Not used)
	0	Switching Signal	Stores Switching Signal status

#### Table 2. Process Data (PDIn)

Table 3 shows an example of process data when the sensor value is 0x00010B4F and the Switching Signal state is 1.

#### Table 3. Example of Process Data

-	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
	1	•		PDIn[0]		4	•	•
Value	0	0	0	0	0	0	0	0
				PDIn[1]				
Value	0	0	0	0	0	0	0	1
				PDIn[2]				
Value	0	0	0	0	1	0	1	1
				PDIn[3]				
Value	0	1	0	0	1	1	1	1
	PDIn[4]							
Value	0	0	0	0	0	0	0	0
	PDIn[5]							
Value	0	0	0	0	0	0	0	1



# 4.4.4 Parameters

The list of parameters to be sent and received with the master by IO-Link is described in Table 4.

#### Table 4. List of Setting Parameters

	of Bits				
Param SP1		(initial value) Switchin	ng Signal	Channel1	
	32	0x00000000	RW	-	Switching Point1 (SP1) setting <sup>note1</sup>
(unsigned int)		to			SP1≥SP2 must be met.
(		0x00FFFFFF			
		(55000) <sup>note2</sup>			
Param SP2	32	0x0000000	RW	-	Switching Point2 (SP2) setting <sup>note1</sup>
(unsigned int)		to			SP1≥SP2 must be met.
, c ,		0x00FFFFFF			
		(45000) <sup>note2</sup>			
Config Logic	8	0, 1	RW	-	Switching state logical setting
(unsigned char)		(0)			0: High active
					Send 1 if ON.
					1: Low active
					Send 0 if ON.
Config Mode <sup>note3</sup> (unsigned char)	8	0, 1, 2, 3 (0)	RW	-	Switching state judgment mode setting
(unsigned char)		(0)			0 : Deactivated
					Disabled, switching state is always OFF
					1 : Single point
					2 : Window
					3 : Two point
,	16	0x0000	R/W	-	Hysteresis
(unsigned sort)		to			
		0xFFFF			
		(0)			
Teach-In Result : state	8	0, 1, 2, 3, 4, 5, 7 (0)	RO	-	Results of the previous Teach-In command
(unsigned char)		(0)			0: Idle,
					1: SP1 Success,
					2: SP2 Success
					3: SP12 Success,
					4: Wait
					5: Busy
					7: Error

Note 1. Refer to section, 4.3 Operating Mode and Switching State.



- 2. The Device Tool sets the value in the range of 0 to 16777215 (0xFFFFF). For the display image, refer to section, 6.6.5 Parameter Tab.
- 3. The default setting is Deactivated. If using switching judgment, change to Windows or Two point. Do not select Single point as it is not supported by this sample application.
- 4. Not supported in this sample application. Do not use.

# 4.5 Peripheral features and Terminals to be Used

The list of peripheral functions used in this sample application is described in Table 5, and the list of pins used is described in

Table 6. List of Terminals Used .

#### Table 5. List of Peripheral Features to be Used

Peripheral Features	Usage
SCI0 (Simplified SPI)	SPI Master for ZIOL2401 communication(used in IO-Link stack)
SCI1 (UART)	UART communication with PC (ZSSC GUI)
IIC	IIC Master for ZSSC communication
AGT0	Cycle timer for IO-Link communication (used in IO-Link stack)

#### Table 6. List of Terminals Used

Terminal Name	I/O	Usage
P411/IRQ4	Input	IO_INT(Interrupt occurs when LOW)
P410	Input	WakeUp detection signal input pin of IO-Link
P409/IRQ6	Input	DC/DC Ready signal input pin of ZIOL2401
P408/SCL	Output	IIC clock pin for ZSSC communication
P407/SDA	I/O	IIC data pin for ZSSC communication
P913	Output	Control of EK board LED3
P914	Output	Control of EK board LED2
P401/TXD	Output	UART TXD for PC (ZSSC GUI) communication
P402/RXD	Input	UART RXD for PC (ZSSC GUI) communication
P304	Output	ZSSC KS5V ON/OFF (ON at L output)
P303	Output	ZSSC KS12V ON/OFF (ON at L output)
P302	Output	IO-Link IO_AUX_TX
P301	Output	IO-Link IO_AUX_EN
P106	Output	Reset control terminal of ZIOL2401 (Reset is released by L output)
P105	Output	Reset control terminal of ZSSC (Reset is released by L output)
P104/IRQ1	Input	EOC (End-Of-Conversion signaling) of ZSSC
P103/SSL0	Output	SPI communication enable/disable control pin of ZIOL2401 (enabled by L output)
P102/SCK0	Output	SPI communication SCK0 of ZIOL2401
P101/MOSI0	Output	SPI communication for ZIOL2401 MOSI0
P100/MISO0	Input	SPI communication for ZIOL2401 MISO0



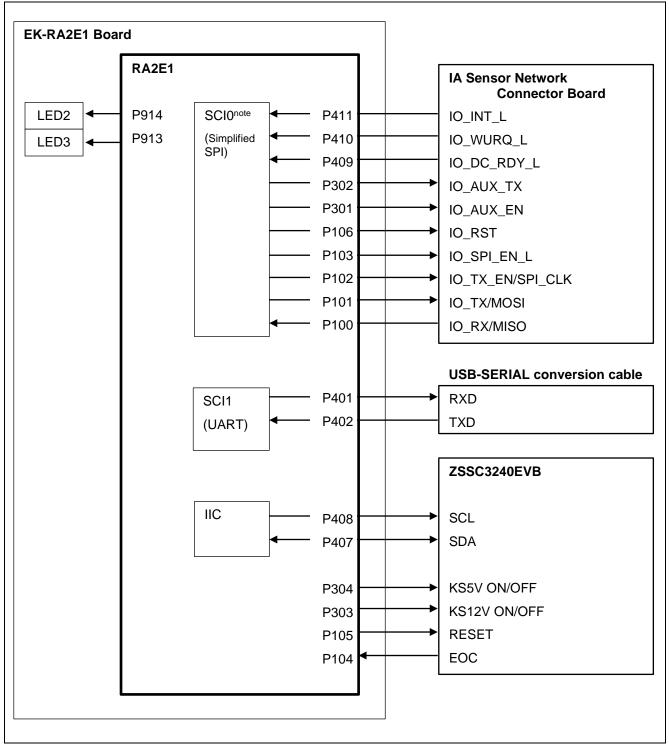


Figure 17. Peripheral Features and Terminals to be Used

Note: The SCI0 simple SPI is controlled by a proprietary driver provided by the IO-Link stack library. It does not use the SCI.SPI driver provided by FSP.



### 4.6 **Program Structure**

#### 4.6.1 File Structure

The TMG IO-Link stack and related files are located in the Library folder. The IO-Link stack manuals are located in the Manuals folder. The file structure in the IO-Link folder is described in Table 7.

#### Table 7. File Structure

Folder name, File name	Description
IO-Link	
Application	Application folder
application.c	Application program
application.h	Application header
define.h	Define header
global.h	Global header
i2c.c	I2C program
i2c.h	I2C header
main.c	Application main
r_led_api.c	LED control program
r_led_api.h	LED control header
spi.c	SPI processing program
spi.h	SPI header
Starterkit_Config.h	Starterkit_Config.h
tool.c	tool function
tool.h	tool function header
uart.c	UART command processing program
uart.h	UART command processing header
utils.h	Utilities header
ZSSC.C	ZSSC processing program, ZSSC measurement
	processing
zssc.h	ZSSC header
BSP	BSP folder for application parts not related to IO-Link
BSPStack.h	User-implemented Hardware Abstraction definitions
IOLD_Config.h	system specific Defines
SystemInit.h	Hardware settings definitions
ZIOL2401.h	Functions for ZMDI L2401
	IODD file store as folder for IO Link devises
	IODD file storage folder for IO-Link devices
TMG-logo.png	TMG Logo Image File IODD1.0.1 File
TMG-RA2E1-Starterkit-20210715-	
IODD1.0.1.xml TMG-RA2E1-Starterkit-20210715-	IODD1.1 File
IODD1.1.xml	
TMG-RA2E1-Starterkit-con-pic.png	M12 connector 4Pin image file
TMG-RA2E1-Starterkit-icon.png	Board icon image file
TMG-RA2E1-Starterkit-pic.png	Board Image File
	ŭ
Library	IO-Link stack library, parameter set storage folder
BSPInterface.h	Defines for the BSP
DeviceAccess.h	Device Access protection
DeviceStack.h	IO-Link Device Stack
DStorage.h	Data Storage for the DeviceStack
DTypes.h	Datatype Definitions



Folder name, File name	Description
EventDispatcher.h	functions for EventDispatching
libIO_Link_Starterkit_RA2E1_lib.a	IO-Link Library for the starter kit solution
ParameterManager.h	Interface to the application framework
Profile_common.h	common Declarations for Profiles
Manuals	Manual folder
TMG IO-Link Device Integration Library	IO-Link Device Evaluation Library
Manual.pdf	
└—StackExtensionsApp	IO-Link related part storage folder of application
BSPExtensions.h	definitions for Stack Extensions Board Support Package
IOLinkMain.c	IO-Link Application
IOLinkMain.h	definitions for main program
MemoryManager.h	definitions for Stack Extensions Memory Manager
ParameterSet.h	Definitions for Stack Extensions
ProductionSettings.h	definitions for Stack Extensions Production Settings

# 4.6.2 Function List

In the following section, only the functions introduced in section, 4.1 Overview of the Overall Processing Flow are described in detail. For other functions, please refer to the source code of the included sample application project.

#### 4.6.2.1 main.c

[Function name] iol\_main

Overview	iol_main function
Header	None
Declaration	int iol_main(void)
Description	It is composed by adding application-specific processing to iol_main() provided by TMG. After initializing the IO-Link stack library and peripheral functions used in the application, it shifts to periodic processing.
Argument	None
Return value	None
Remarks	None

#### 4.6.2.2 IOLinkMain.c

[Function name] iolink\_main

Overview	IO-Link main processing
Header	IOLinkMain.h
Declaration	TUnsigned8 iolink_main(void)
Description	Call the STACK_Run function. Periodically calls the IO-Link Stack to get the status.
Argument	None
Return value	State of the IO-Link stack
	STACK_STATUS_SIO :
	IO-Link connection is SIO mode
	STACK_STATUS_STARTUP :



	Master is detected and device is in startup state
	STACK_STATUS_PREOPERATE :
	Device is in pre-operating state
	STACK_STATUS_OPERATE :
	Device is in working state
	STACK_STATUS_DISCONNECTED :
	Disconnected state, device waits for next wake-up in IO-Link mode
Remarks	None

# 4.6.2.3 application.c

[Function name] apl\_main

Overview Header Declaration Description	Application main application.h void apl_main(void) Call UART_Command_Check() to check whether UART command is received. When UART command is received, call UART_Command_Execute() to process the
	UART command. If there is no UART command reception for 1 second, call zssc_measurement_reset() and then shift to ZSSC measurement processing. zssc_measurement() is called periodically to measure ZSSC as long as there is no UART command reception. If a UART command is received, the ZSSC measurement process is terminated immediately.
Argument	None
Return value	None
Remarks	None

[Function name] App\_SensorValue

Overview	IO-Link application processing using sensor values		
Header	None		
Declaration	static bool App_SensorValue (TUnsigned32 sensorValue)		
Description	Execute the following three processes.		
	1. Creating process data		
	2. Teaching process (threshold setting process)		
	3. Switch point processing		
Argument	Measurement		
Return value	Switching judgment result		
	false :		
	Out of valid range (OFF)		
	true :		
	Within valid range (ON)		



# RA2E1 Group

RemarksThis function is an internal function called by the apl\_main function.While the Teaching process is in progress, the return value will be false.

### 4.6.2.4 uart.c

[Function name] UART\_Command\_Check

Overview	UART command reception check		
Header	uart.h		
Declaration	uint8_t UART_Command_Check(uint8_t *buffer)		
Description	Check if the command is received from the ZSSC GUI.		
Argument	buffer Buffer top pointer		
Return value	Reception status		
	0: Command not received		
	1: Command received		
Remarks	None		

#### [Function name] UART\_Command\_Execute

Overview	UART command execution		
Header	uart.h		
Declaration	void UART_Command_Execute(uint8_t *buffer)		
Description	Execute the command received from the ZSSC GUI. When a measurement command is executed, the measurement result is stored in the global variable sensor_value.		
Argument	buffer Buffer top pointer		
Return value	None		
Remarks	None		

#### 4.6.2.5 zssc.c

[Function name] zssc\_measurement

Overview	ZSSC measurement
Header	zssc.h
Declaration	bool zssc_measurement(void)
Description	The AA <sub>HEX</sub> command performs ZSSC measurement and stores the measurement result in the global variable sensor_value.
Argument	None
Return value	true
Remarks	For the AA <sub>HEX</sub> command, refer to the following materials. • ZSSC3240 Evaluation Kit User Manual • ZSSC3240 Data Sheet



#### 4.6.2.6 r\_led\_api.c

[Function name] R\_LED\_Control

Overview	Control of LED
Header	r_led_api.h
Declaration	void R_LED_Control (uint16_t led_pin, bool state)
Description	Turns on / off the LED.
Argument	led_pin LED Pin number
Argument	state LED status
	false: OFF
	true: ON
Return value	None
Remarks	None

# 5. Sample Project Execution Method

This chapter describes the steps for importing a sample project and executing the program.

# 5.1 Importing Sample Projects

- 1. Start e<sup>2</sup> studio.
- 2. Enter a new workspace name in the Workspace dialog box. Then click Launch.

😰 e² studio Launcher		×
Select a directory as workspace		
e <sup>2</sup> studio uses the workspace directory to store its preference:	s and development artifacts.	
Workspace: C:\Users\Renesas\e2_studio\workspace	✓ <u>B</u> rowse	
Use this as the default and do not ask again		
	Launch Cancel	
	Launch Cancel	

Figure 18. Start Using a New Workspace

3. Click on Import existing projects.



# RA2E1 Group

Edit Source Refactor Navigate Search Project Renesas V	/iews <u>R</u> un <u>W</u> indow <u>H</u> elp	
Nelcome ×		🛅 🗘 🗘 🖈 🛣 🗖 🧧
RENESAS Welcome to e <sup>2</sup> :	studio	Hide
Create a new C/C++ project Create a new e <sup>2</sup> studio C/C++ project		view overview of the features
Import existing projects Import existing er studio projects from or archive	n the filesystem For the Go thr	rials ough tutorials
Import sample projects Download and import sample projects website	from Renesas	<mark>ples</mark> t the samples
Review IDE configuration sett Review the IDE's most fiercely contest	tings Find o	t <sup>i'</sup> S <mark>New</mark> ut what is new
Open an existing file Open a file from the filesystem		Start Guides y getting familiar with the tool
		Always show Welcome at start

Figure 19. Welcome to e<sup>2</sup>studio

- 4. Click Select archive file, then click **Browse** to open the location of the sample project zip file.
- 5. Select the zip file of the sample project and click **Finish**.

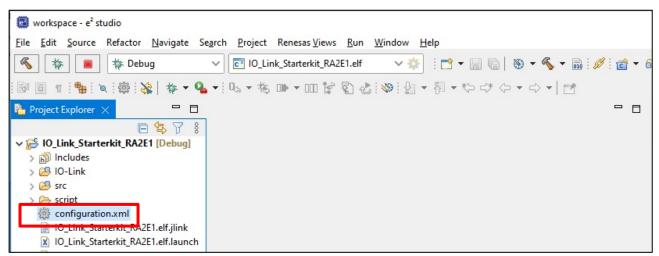
S Import	
Import Projects Select a directory to search for existing Eclipse projects.	
◯ Select root directory:	Browse
$\odot$ Select <u>a</u> rchive file: C:\Users\Renesas\Downloads\IO_Link_Starte $\checkmark$	B <u>r</u> owse
Projects:	
□ IO_Link_Starterkit_RA2E1 (IO_Link_Starterkit_RA2E1/)	Select All
	Deselect All
[ [	R <u>e</u> fresh
Options  Search for nested projects  Copy projects into workspace  Close newly imported projects upon completion  Hide projects that already exist in the workspace	
Working sets	
Add project to working sets           Working sets:	Ne <u>w</u> S <u>e</u> lect
?	Cancel

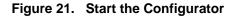
Figure 20. Importing Sample Projects



### 5.2 Build the Project

1. After the sample project is imported, double-click configuration.xml to open the configurator.





2. Click **Generate Project Content** on the **Stacks** tab. The configurator generates the necessary files and adds them to the project.

workspace - IO_Link_Starterkit_RA2E1/configuration.xml - e <sup>2</sup> studio			
File Edit Source Refactor Navigate Se	arch Project Renesas Views Run Window Help		
🐔 🗱 🔳 🗱 Debug	✓ IO_Link_Starterkit_RA2E1.elf ✓ ↔ III IO_Link_Starterkit_RA2E1.elf ✓ ↔ III IO_Link_Starterkit_RA2E1.elf		
🗈 🗉 n 1 🏪 🔍 🗇 🐝 🛛 🚸 🕶 💁	▼! 04 ★ 徐 ■ ▼ 目 12 02 100 100 100 100 100 100 100 100 1		
Project Explorer 🗙 🗖 🗖	🗱 [IO_Link_Starterkit_RA2E1] FSP Configuration 🗙		
□ 🛱 🍸 🖇 ✓ 👺 IO_Link_Starterkit_RA2E1	Stacks Configuration Generate Project Content		
<ul> <li>) [] Includes</li> <li>) [29] IO-Link</li> <li>&gt; [29] src</li> <li>&gt; [29] script</li> <li>[30] Configuration.xml</li> <li>[31] IO_Link_Starterkit_RA2E1.elf.jlink</li> <li>[32] IO_Link_Starterkit_RA2E1.elf.launch</li> <li>[33] IO_Link_Starterkit_RA2E1 Debug_Flat.</li> <li>[33] IO_Link_Starterkit_RA2E1 Debug_Flat.</li> <li>[33] R7FA2E1A92DFM.pincfg</li> <li>[34] ra_cfg.txt</li> </ul>	Image: Second state of the second		
<ul> <li>is_cry.txt</li> <li>version_history.txt</li> <li>Overeloper Assistance</li> </ul>	New Object >		
	Objects     Remove       Summary     BSP       Clocks     Pins       Interrupts     Event Links       Stacks     Components		

Figure 22. Generate Project Content



#### RA2E1 Group

3. Click the Build icon to build the project.

📴 workspace - IO_Link_Starterkit_RA2E1/conf	figuration.xml - e <sup>2</sup> studio		
File Edit Source Refactor Navigate Se	earch Project Renesas Views Ru	in Window Help	
🔦 🔯 🔳 🕸 Debug	V IO_Link_Starterkit_RA2E1.e	lf 🔷 🔅 🗄 🕶 🔚 🕼   🛞 🕶 🗞 🖛 🗒 🖉	1 🔂 🕶 6
📴 📴 📲 🔍 😳 💸 🛛 🕸 🗕 🥵	•10₀ • 卷 ⊪ • Ⅲ ≌ 🖏	८:00:2 - २ - २ - २ - 2	
Project Explorer 🗙 🗖 🗖	🔅 [IO_Link_Starterkit_RA2E1] FSP (	Configuration $ imes$	
□ ♀ ♡ 8 ✓ B IO_Link_Starterkit_RA2E1	Stacks Configuration	Generate Project	t Content
> 🔊 Includes > 😕 IO-Link > 😂 ra	Threads	HAL/Common Stacks 🔄 New Stack > 🚔 Extend Stac	k >
> 🔑 ra_gen > 🔑 src > 🍃 Debug > 🍃 ra_cfg > 🍃 script 	<ul> <li>✓ AL/Common</li> <li> <i>G</i>_ioport I/O Port (r_i          </li> <li> <i>G</i>_flash0 Flash (r_flas         </li> <li> <i>G</i>_i2c_master0 I2C M         </li> <li> <i>G</i>_uart UART (r_sci_u         </li> </ul>	<ul> <li> <i>g_ioport I/O Port</i>         (<i>r_ioport</i>)         (<i>i</i>)         (<i>i</i>)</li></ul>	() ()

Figure 23. Build the Project

4. When the build finishes successfully, the following output is generated.

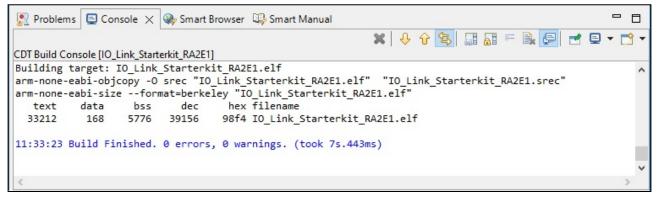


Figure 24. Output on a Successful Build



# 5.3 Setting up a Debug Connection between the EK-RA2E1 Board and the Host PC

The following graphic shows how to connect the EK-RA2E1 board to a host PC with a USB cable and download the program via the debug interface.

- 1. Connect the USB cable from the PC to the USB debug port (J10) on the EK-RA2E1 board.
- 2. Confirm that the debug LED (LED5) is lit orange.

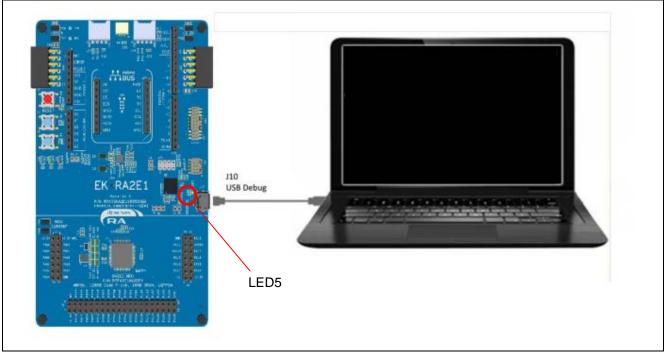


Figure 25. Connect the Board's USB Debug Port (J10) to the Host PC

# 5.4 Writing Sample Projects to the MCU

1. Click the Debug icon.

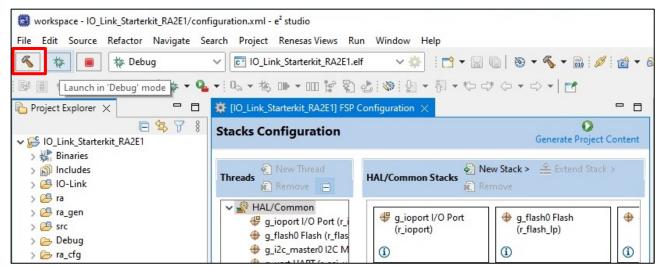


Figure 26. Launch in Debug Mode



2. You may receive a firewall warning for 'e2- server-gdb.exe'. Check the **Private networks, such as my** home or work network checkbox and click **Allow access**.

	394 - 552	rity Alert ws Defenc	ler Firewall has blocked some features of this	×
Windows I networks.		Firewall has bl	ocked some features of E2 Server GDB on all public and private	
		Name:	E2 Server GDB	
		Publisher:	Renesas Electronics Europe Ltd	
Allow FR C		Pat <u>h</u> :	C:¥users¥renesas¥.eclipse ¥com.renesas.platform_1267172996¥debugcomp¥ra¥e2-	
			ate on these networks:	
I∕ P <u>r</u> iv	ate netwo	orks, such as r	ny home or work network	
Put bec	olic networ ause thes	ks, such as th e networks of	ose in airports and coffee shops (not recommended ten have little or no security)	
What are	the risks o	of allowing an a	app through a firewall?	
			Allow access Cancel	

Figure 27. Firewall Warning

3. A dialog may appear prompting you to switch to the debug perspective. Click **Switch** to switch views.

G C0	nfirm Perspective Switch X
?	This kind of launch is configured to open the Debug perspective when it suspends. This Debug perspective supports application debugging by providing views for displaying the debug stack, variables and breakpoints.
	Switch to this perspective?
Ren	nember my decision
	<u>S</u> witch <u>N</u> o

Figure 28. Confirm Perspective Switch



#### RA2E1 Group

#### 4. The sample project is written to the MCU and the screen changes as shown in Figure 29.

workspace - IO_Link_Starterkit_RA2E1/ra/fsp/src/bsp/cmsis/Devic	
File Edit Source Refactor Navigate Search Project Renes	sas Views Run Window Help
🔦 🐐 🔳 🔅 Debug 🗸 🕞 IO_Link_Start	terkit_RA2E1.elf 🛛 🗸 🌞 📄 🔫 🔚
🔌 📭 🗉 🛢 💦 💀 📀 🕼 🖬 🤜 🐼 💆 🖈 🕶	Q : U 🎋 🕪 - 💷 🕍 🖏 👌
a los on a set set a los a set	
Resume (F8)	
Resume (F8)	SystemInit();
Resume (F8)         Solution Debug ×       □       i⇒       8       □       Ic startup.c ×         Solution Operation Control (Control (Contro) (Control (Control (Control (Control (Control (Control (Control	<pre>SystemInit();</pre>
Resume (F8)         Image: Startup of the start st	

Figure 29. Writing to MCU Completed

#### 5.5 Start the Program

- 1. In the state shown in Figure 29, click the F8 or Resume icon to start running the program.
- 2. Stop once at the beginning of the main() function. Click F8 or Resume icon again.
- 3. The program is now running and 'Running' is displayed in e<sup>2</sup>studio status bar.

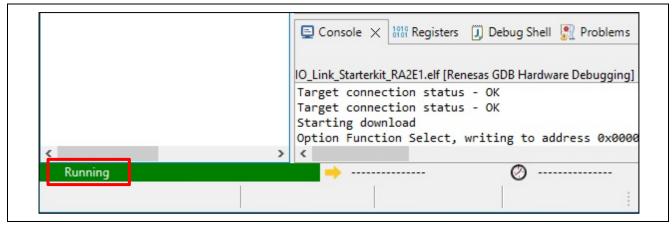


Figure 30. Start the Program



## 6. IO-Link Device Tool Usage and Functions

In this section, it is assumed that the TMG IO-Link Device Tool V5.1 – PE is installed on the Windows<sup>®</sup> PC, and the preparation for use and the explanation of the functions are described. Refer to section, 3 Hardware for details.

### 6.1 IO-Link Device Tool V5.1 - Start PE

The **Topology** pane shown in Figure 31 displays the topology from the PC to the IO-Link device.

The Device Catalog shows all devices that have been imported and are available for use.

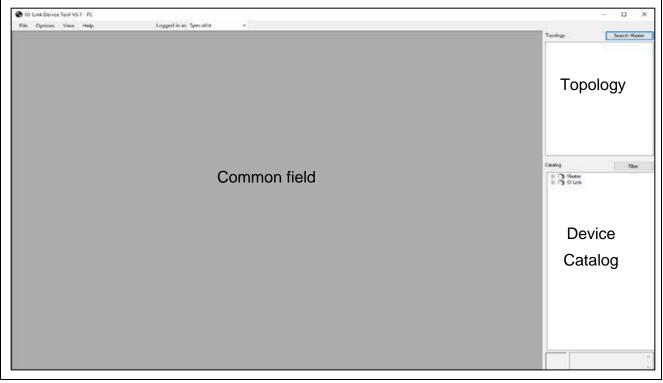


Figure 31. IO-Link Device Tool V5.1 – PE



### 6.2 Update IO-Link Device Catalog

- 1. Select Options from the menu bar, and then select "Import IODD (IO Device Description)".
- 2. Enter directly or browse to select the path of the folder where the IODD file is located. The IODD files used in this sample project are stored in the IODD folder of the sample project. By setting the path to this folder as shown in Figure 32, available IODD files can be automatically detected.
- 3. Check TMG-RA2E1-Starterkit-20210715-IODD1.1.xml.

IODD     Subdirectory     Vendor ID     Devic       TMG-RA2E1-Starterkit-20210715-IODD1.0.1.xml     0x014F     0x041	C:¥Users¥Renesas¥Downloads¥IO_Link_Starterkit_RA2	2E1¥IO-Link¥IODD	×	. IODDFinder
MG-RA2E1-Starterkit-20210715-IODD1.0.1.xml 0x014F 0x041	Vendor ID Device ID	Revision all 🗸		include subdirector
		Subdirectory	Vendor ID	Device ID
MG-RA2E1-Starterkit-20210715-IODD1.1.xml         0x014F         0x041			0x014F	0x041011
	G-RA2E1-Starterkit-20210715-IODD1.1.xml		0x014F	0x041011

Figure 32. IO-Link Device Tool V5.1 – PE (Load the IODD file)

4. Select Import.

## 6.3 Update IO-Link Master Catalog

- 1. Select Options in the menu bar, and then select Import IOLM(IO-Link Master Description).
- 2. When Figure 33 is displayed, select **TMG WEB**.

ath			· · · · · · · · · · · · · · · · · · ·	~	TMG WEB
ilter	Vendor ID Device ID	Fieldbus			include subdirect
10	DLM		Subdirectory	Vendor ID	Device ID

Figure 33. IO-Link Device Tool V5.1 – PE (Import IOLM)



#### 3. When the screen changes and the list of IOLM is displayed, select "..." button of Vendor ID.

r			local				
Import from TMG Web Server							
Filter Vendor ID	Fieldbus						
IOLM	Subdirectory	Vendor ID	Device ID	1			
Balluff-BNI-ECT-507-005-Z040-20151110-IOLM1.3		0x0378	0x535216				
Balluff-BNI-ECT-527-005-Z040-20151110-IOLM1.3		0x0378	0x535816				
Balluff-BNI-EIP-502-105-R015-20151110-IOLM1.3		0x0378	0x525043				

## Figure 34. IO-Link Device Tool V5.1 – PE (Vendor ID)

#### 4. When the Vendor ID Table appears, select "Pepperl + Fuchs GmbH (0x0001)".

Balluff (0x0378)	
Baumer Electric AG (0x015E)	
Belden Deutschland GmbH – Lumberg Automation (0x016A)	
Carlo Gavazzi (0x0380)	
li-soric GmbH & Co. KG (0x0221)	
lobau GmbH & Co. KG (0x041E)	
merson Automation Solutions (0x0026)	
Indress-Hauser (0x0011)	
EIG ELECTRONIC GmbH (0×055D)	
fm electronic gmbh (0x0,136)	
euze electronic GmbH (0x0152)	
Aolex (0x0127)	
Murrelektronik GmbH (0×012F)	
Parker Hannifin (0x010E)	
Pepperl+Fuchs GmbH (0x0001)	
Sick AG (0x001A)	
MC Corporation (0x0083)	
MG (0×2DCF)	
MG TE GmbH (0×014F)	
Furck (0x013D)	
VAGO Kontakttechnik GmbH & Co. KG (0x011D)	
venglor sensoric GmbH (0×0057) Zimmer GmbH (0×0344)	

#### Figure 35. IO-Link Device Tool V5.1 – PE (Vendor ID Table)

4. The available IOLM files are detected.



#### 5. Check "Pepperl + Fuchs-IO-Link-Master02-USB-20200517-IOLM 1.4".

				Import	from TMG Web	Server		local
lter	Vendor ID	0×0001	Device ID		Fieldbus			
IOL	LM					Subdirectory	Vendor ID	Device ID
Pep	perl-Fuchs-ICE	1-8IOL-G60L-V1	ID-EIP-20200521	1-IOLM1.4			0x0001	0x010034
Pepperl-Fuchs-ICE1-8IOL-G60L-V1D-PN-20200521-IOLM1.4							0x0001	0x020050
Pepperl-Fuchs-ICE1-8IOL-G30L-V1D-EIP-20200521-IOLM1.4							0x0001	0x01003B
Pepperl-Fuchs-ICE1-8IOL-G30L-V1D-PN-20200521-IOLM1.4					0x0001	0x020051		
Pep	perl-Fuchs-IO-I	ink-Master02-U	SB-20200517-IO	LM1.4			0x0001	0x000001

#### Figure 36. IO-Link Device Tool V5.1 – PE (Load the IOLM file)

6. Select Import.



## 6.4 Check for Catalog Updates

After successfully updating the Catalog in sections 6.2 and 6.3, the TMG TE GmbH vendor and the IO-Link device board with EK-RA2E1 will appear in the IO-Link Devices section of the Catalog as **RA2E1 Starterkit**. The IO-Link-Master02-USB appears under Master.

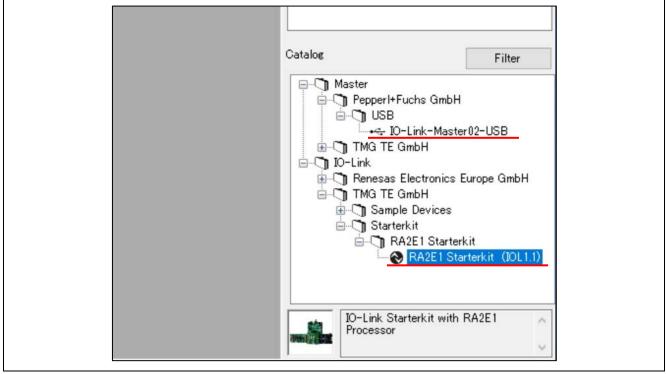


Figure 37. IO-Link Device Tool V5.1 – PE (Check for Catalog Updates)

## 6.5 Setup for IO-Link communication

1. Click the **Search Master** button in the upper right corner of the window. "**IO-Link-Master02-USB**" will appear in the **Master Discovery** window as shown in Figure 38.

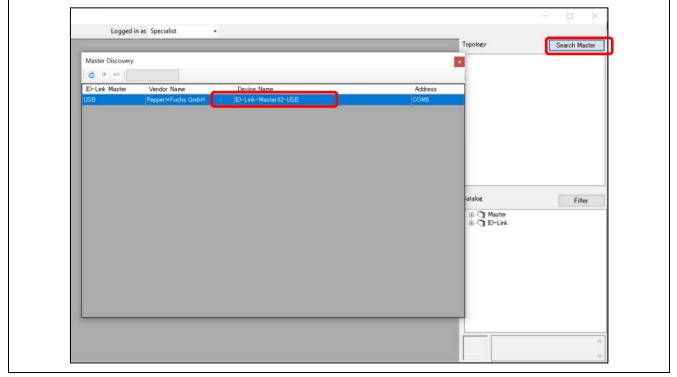


Figure 38. IO-Link Device Tool V5.1 – PE (Search for IO-Link Master)



- 2. Double-click on the device name displayed in the **Master Discovery** window.
- 3. Click on the **Go Online** button to activate the connection between the Master and the device.

EPEPPERL+FUCHS	Vendor IO-Link Vendor ID	PepperI+Fuchs GmbH 0x0001		
Product	Product name Description	ID-Link-Master02-USB USB to IO-Link master		
CC III	IOLM IOLM Revision FW Revision	Papperl-Fuchs-10-Link-Master02-USB-202005 5.1.1 3.0F/1.3.1	17-IOLM1.4xml IOLM Device ID	0x000001
Main Communication Interface	Fieldbus Vendor ID	0×2843	Fieldbus Device ID	0×0201
	COM Port	COM6 Unique Identifie	er USB¥VID_2843&PID_02	201¥3701912502

Figure 39. IO-Link Device Tool V5.1 – PE (Set to Online State)

Once the connection between the Master and the device is active, the **Go Online** button will be replaced by a button with a red circle and the **Check Devices** button will be enabled.

4. Click on the Check Devices button to detect the connected devices.

Port         Mode         Vendor         Device           0.4         IO-Link         IO-Link         IO-Link           0.2         IO         IO         IO	0 I
0,4 🕑 IO-Link	
	0
Port Config Details	
- Port Config Details	
Vendor ID         Device ID         Product ID         IO-Link: Mode           IODD	no check

Figure 40. IO-Link Device Tool V5.1 – PE (Check the IO-Link Device)



When the detection is complete, the **Check Devices** window will appear and show the RA2E1 Starterkit connected to the IO-Link Master port.

Check I	Devices				
	IL	Engineering	Rev	IO-Link Master	Rev
	n			RA2E1 Starterkit	1.1
0	n				
			Takeov	er devices into engineering	Exit

Figure 41. IO-Link Device Tool V5.1 – PE (Detect IO-Link Device)

5. Click on the **Takeover devices to engineering** button.

When the connection between the master and the device is successful, **RA2E1 Starterkit** is added to the list of devices connected to the IO-Link Master as shown in Figure 42.

Port 0, 4 0, 2	۲	Mode IO-Link	Vendor	Device		0 I
			TMG TE GmbH	RA2E1 Starterkit		
	0	DI		I TOTAL I STATISTICATION		0
-Port Config						
Port Config I	Details					
Vendor ID	0-0145	Device ID	0x041011 Product ID	RA2E1-01	IO-Link Mod	e no check

Figure 42. IO-Link Device Tool V5.1 – PE (Connect IO-Link Master and Device Successfully)

6. Double click on RA2E1 Starterkit and Common will appear.

## 6.6 EK-RA2E1 Board Sensor Demo of IO-Link Device Tool

This section explains how to operate IO-Link devices using the EK-RA2E1 board from the IO-Link Device Tool. The device operation toolbar is located in the upper left corner of Figure 43.

😵 RA2E1 Starterkit 🛛 @ IO-Link-Master02-	USB (COM6)[0, 4]		
📃 🔜 🕂 🕈 🕇 block write mo	de 🔹		
Overview	bservation Parameter	Diagnosis Scope Generic IODD	
	Vendor	TMG TE GmbH	
🚷 IO-Link	Vendor Text	TMG TE GmbH	Technologie Management Gruppe
	Vendor ID	0x014F URL http://www.tmgte.com	Technologie und Engineering

Figure 43. Sensor's Description Page



Figure 44 shows the buttons on the device operation toolbar and their functions.

📃 🕂 🛧 🛧 direct write mode 🕞
: System Operation Status
: Download the variable changes to the device (Download to device)
: Upload variable information from device (Upload from device)
: Enable dynamic updating of variables
direct write mode   i direct write mode -> Download changed variables to the device automatically
block write mode -> Download changed variables to the device manually

Figure 44. IO-Link Device Tool V5.1 – PE (Device Operation Toolbar)

Note: If the communication status of the master is not possible, the **System Operation Status** icon may be displayed in gray. In this case, reconnecting power to the master board and restart the device tool to improve the situation.

#### 6.6.1 Common Tab

The Common tab displays general descriptive information about the device, as follows.

Vendor: TMG TE GmbH

Vendor Text: TMG TE GmbH

Vendor ID: 0x014F

URL: www.tmgte.com

Device: RA2E1 Starterkit

Description: IO-Link Starterkit with RA2E1 Processor

**Device ID**: 0x041011

IO-Link Revision: 1.1

SIO mode: No

Communication baud rate: COM2

Minimum cycle time of sensor: 6400[us]

Photo of IO-Link device

**Connection description** 

Pin layout of M12 connector



_ ⊞ + + ·	block write mod	e •							
mmon Process Da	ata Identification Ob	servation Parameter	Diagnosis Scop	e Generic I	ODD				
Overview									
-		Vendor	TMG TE G	mbH					
<b>@ IO</b> -	link	Vendor Text	TMG TE G	mbH					Technologie Management Gruppe
• -•		Vendor ID	0×014F	URL	http://	/www.tmgte.co	m	لى ا	Technologie und Engineering
Device	RA2E1 Starter	kit							
Description	IO-Link Starte	rkit with RA2E1 Process	or					~	
									AND
								<b>-</b>	
evice ID	0×041011	IO-Link Revision	1.1	SIO n	node	no			
litrate	COM2	MinCycleTime	6400						
IO Device Descriptio	210								
ODD TM	IG-RA2E1-Starterkit-2	0210715-IODD1.1×ml				Revision	V1.1	Date	2021-07-15
Connection	12 connector with cable	15 m							
Description	12 CONNECTOR WITH CADIE	5 1.0 11						^	2.
								_ (	
nb name	functio	on		color				_^ (3	• 1•
2	Lplus NC			3N WH				-	10
3	Lminus			wн 3U				- `	4•
4	CQ			3К				~	M12-4

Figure 45. IO-Link Device Tool V5.1 – PE (Common tab)



#### 6.6.2 Process Data tab

The **Process Data** tab displays information on PD Input.

- 1. PD Input
  - MDC Measurement Value Sensor measurement value
  - MDC Scale Unsupported
  - SSC.1 Switching Signal<sup>\*</sup>
     Switching state (Low or High)
  - SSC.2 Switching Signal Unsupported

	A6)[0, 4]		
📕 📑 🕂 🕈 🛧 block write mode	-		
mmon Process Data Identification Observation	Parameter Diagnosis	Scope Generic IODD	
ame		Value	Unit
·] PD Input			
MDC - Measurement Value		40658	
MDC - Scale		0	
SSC.1 – Switching Signal		Low	0
SSC.2 - Switching Signal		Low	0

## Figure 46. IO-Link Device Tool V5.1 – PE (Process Data Tab)

Note\*: SSC.1 - Switching Signal works only with the green LED. Red LED is not supported.



## 6.6.3 Identification Tab

The Identification tab allows the user to read and review the identification information stored on the device, such as.

- 1. Device information
- 2. Application-specific information
- 3. Revision information

ommon Process Data Identification Observation Parameter Diagnosis Scope Ger	neric IC	DD		
Name	R/W	Value	State	Unit
iendor Name	ro	TMG TE GmbH	i	
iendor Text	ro	www.tmgte.com	i	
roduct Name	ro	RA2E1 Starterkit	i	
roduct Text	ro	IO-Link Starterkit with RA2E1 Processor	i	
roduct ID	ro	RA2E1-01	i	
erial Number	ro		е	
ardware Revision	ro		e	
irmware Revision	ro		e	
pplication-specific Tag	rw	***	i	
unction Tag	rw	***	i	
ocation Tag	rw	***	i	

Figure 47. IO-Link Device Tool V5.1 – PE (Identification tab)



## 6.6.4 Observation Tab

The **Observation** tab displays the measurements taken by the device. The user can review the information measured by the device.

Name	R/W Value	State Unit
- ] PD Input		
PD Input.MDC - Measurement Value	ro	e
PD Input.MDC - Scale	ro	e
PD Input.SSC.1 - Switching Signal	ro	e
PD Input.SSC.2 - Switching Signal	ro	e

Figure 48. IO-Link Device Tool V5.1 – PE (Observation tab)



## 6.6.5 Parameter Tab

The **Parameter** tab displays the parameter setting status of the device and allows the user to check the status of the device from here. It also allows the user to write new settings to the device. Please refer to Table 4 for the meaning and features of the parameters. For details on how to set parameters of the device, please refer to section, 6.6.7 Change Device Parameters (Teach-In/Read).

RA2E1 Starterkit @ IO-Link-Master02-USB (COM6)[0, 4] ■ 王 + ↑ ↑ I block write mode				
Common Process Data Identification Observation Parameter Diagnosis Scope	Gonoria IO	DD		
Name	R/W	Value	State	Unit
[-] General Settings	10 11	Volue	Oldic	Onix
System Command	wo	Application Reset		
[-] Device Parameterisation				
User Variable UInt8_1	rw	0	i	
User Variable UInt8 2	rw	0	i	-
User Variable UInt8_3	rw	User Variable UInt8_3 Enumeration Value 0	• i	
User Variable UInt8 4	rw	User Variable UInt8_4 Enumeration Value 0	• i	
User Variable UInt16_1	rw	-	i	
User Variable UInt16_2	rw	0	i	
User Variable UInt16_3	rw	0	i	
User Variable UInt16_4	rw	0	i	
User Variable UInt32_1	rw	0	i	
User Variable UInt32_2	rw	0	i	
User Variable UInt32_3	rw	0	i	
User Variable UInt32_4	rw	0	i	
[-] Switching Signal Channel 1				
SSC.1 Param.SP1	rw	55000	i	
SSC.1 Param.SP2	rw	45000	i	
SSC.1 Config.Logic	rw	High active	• i	
SSC.1 Config.Mode	rw	Deactivated	• i	
SSC.1 Config.Hyst	rw	0	i	
[-] Switching Signal Channel 2				
SSC.2 Param.SP1	rw	0	i	
SSC.2 Param.SP2	rw	0	i	
SSC.2 Config.Logic	rw	High active	• i	
SSC.2 Config.Mode	rw	Deactivated	• i	
SSC.2 Config.Hyst	rw	0	i	
[-] Teach				
Teach Select	rw	Default Channel	• i	
[-] Teach - Single Value				
System Command	wo	Teach SP1		
System Command	wo	Teach SP2		
Teach Result.State	ro	Idle	i	

Figure 49. IO-Link Device Tool V5.1 – PE (Parameter tab)



## 6.6.6 Scope tab

The **Scope** tab allows the user to visualize the processed data.



Figure 50. IO-Link Device Tool V5.1 – PE (Scope tab)

The user can open the Scope configuration settings by right-clicking in the Scope area. The settings can also be edited.

Visible	Ю	Name	Digital	Value Min	Value Max	Display Min	Display Max	Color
	Ι	MDC - Measurement Value		0	65535	25	90	black
	Ι	MDC - Scale		-100	100	25	50	red
$\checkmark$	I	SSC.1 – Switching Signal		0	1	10	40	green
	I	SSC.2 - Switching Signal		0	1	75	100	blue

Table 8. IO-Link Device Tool V5.1 – PE (Scope tab, Scale/Parameter Settings)



#### 6.6.7 Change Device Parameters (Teach-In/Read)

When the user opens the **Parameter** tab, the device-specific parameters are displayed in the Value column. These values are recorded in the IODD file. For details on the **Parameter** tab, refer to section, 6.6.5 Parameter Tab.

When setting SetPoint (SP1, SP2, so forth) to a device, make sure "Device Access Locks" is set to false; if it is true, setting the parameter to the device will fail. The SetPoint parameter can be set using the "Teach Values" parameter or by using the "Standard Command".

Users can change parameter settings with the IO-Link Device Tool. The settings depend on the write mode. The method is shown below.

#### 6.6.7.1 Set parameters in Teach Values (block write mode)

In this block write mode, the user can change the parameters and then click the **Download to device** button to set the parameters to the device.

- 1. Change the write mode to **block write mode**.
- 2. To set the SetPoint, click on the Value field of the parameter SSC.1 Param.SP1 or SSC.1 Param.SP2.
- 3. Enter the values and press **Enter** on the keyboard. The yellow background color of **Statue** indicates that the parameter has not yet been set in the device.
- 4. To write the parameters, click the Download to device button.
- 5. The green background color of **State** indicates that the synchronization between the master and the device was successfully performed.

📃 📑 🕂 ↑ ↑ Iblock write mode 🔹 🕂 🕂					
Common Process Data Identification Observation Parameter Diagnosis Scope Ge	neric IC	DD			
Name Download to device	R/W	Value		State	Unit
[-] General Settings					
System Command	wo	Application Reset			
[-] Device Parameterisation					
User Variable UInt8_1	rw	0		d	
User Variable UInt8_2	rw	0		d	
User Variable UInt8_3	rw	User Variable UInt8_3 Enumeration Value 0	•	d	
User Variable UInt8_4	rw	User Variable UInt8_4 Enumeration Value 0	-	d	
User Variable UInt16_1	rw	0		d	
User Variable UInt16_2	rw	0		d	
User Variable UInt16_3	rw	0		d	
User Variable UInt16_4	rw	0		d	
User Variable UInt32_1	rw	0		d	
User Variable UInt32_2	rw	0		d	
User Variable UInt32_3	rw	0		d	
User Variable UInt32_4	rw	0		d	
[-] Switching Signal Channel 1					
SSC.1 Param.SP1	rw	50000		с	
SSC.1 ParamSP2	rw	45000		d	
SSC.1 Config.Logic	rw	High active	-	d	
SSC.1 Config.Mode	rw	Deactivated	-	d	
SSC.1 Config.Hyst	rw	0		d	

Figure 51. IO-Link Device Tool V5.1 – PE (Set Parameters in Block Write Mode)



## 6.6.7.2 Parameter Setting Using Direct Write Mode

In this direct write mode, parameter changes are automatically set to the device.

- 1. Change the write mode to **direct write mode**.
- 2. To set the SetPoint, click on the Value field of the parameter SSC.1 Param.SP1 or SSC.1 Param.SP2.
- 3. Enter the values and press Enter on the keyboard.
- 4. The **State** will turn yellow and then green to indicate that the parameters have been set in the device and the master and device are synchronized.

📃 📑 🕂 🕈 🕈 direct write mode 🔹 🔸					
Common Process Data Identification Observation Parameter Diagnosis Scope (	ieneric	IODD			
Name	R/W	Value		State	Unit
[-] General Settings					
System Command	wo	Application Reset			
[-] Device Parameterisation					
User Variable UInt8_1	rw	0		d	
User Variable UInt8_2	rw	0		d	
User Variable UInt8_3	rw	User Variable UInt8_3 Enumeration Value 0	•	d	
User Variable UInt8_4	rw	User Variable UInt8_4 Enumeration Value 0	•	d	
User Variable UInt16_1	rw	0		d	
User Variable UInt16_2	rw	0		d	
User Variable UInt16_3	rw	0		d	
User Variable UInt16_4	rw	0		d	
User Variable UInt32_1	rw	0		d	
User Variable UInt32_2	rw	0		d	
User Variable UInt32_3	rw	0		d	
User Variable UInt32_4	rw	0		d	
[-] Switching Signal Channel 1					
SSC.1 Param.SP1	rw	50000		d	
SSC.1 Param.SP2	rw	40000		с	
SSC.1 Config.Logic	rw	High active	-	d	
SSC.1 Config.Mode	rw	Deactivated	•	d	
SSC.1 Config.Hyst	rw	0		d	

Figure 52. IO-Link Device Tool V5.1 – PE (Set Parameters in Direct Write Mode)



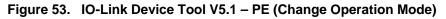
## 6.6.7.3 Change Operation mode

The operating mode is set to **Deactivated** as the initial value. To enable the switching state function using SetPoint, change the operation mode to **Window** or **Two point**.

For details on the operating modes, refer to section, 4.3 Operating Mode and Switching State.

- 1. Change the write mode to **block write mode**.
- 2. Select **Window** or **Two point** in the list of SSC.1 Config.Mode.
- 3. Click the Download to device button to set the device.

[-] Switching Signal Channel 1			
SSC.1 Param.SP1	rw	55000	d
SSC.1 Param.SP2	rw	45000	d
SSC.1 Config.Logic	rw	High active	- <b>-</b> d
SSC.1 Config.Mode	rw	Deactivated	✓ d
SSC.1 Config.Hyst	rw	Deactivated Single point	d
[-] Switching Signal Channel 2		Window	
SSC.2 Param.SP1	rw	Two point U	d
SSC.2 ParamSP2	rw	0	d



Note: Single point is not supported in this sample application. Do not select it.



#### 6.6.7.4 SetPoint settings by Device Measurement Value

Set the value measured by the device to SP1 and SP2 as SetPoint.

 Click the Teach SP1 button or the Teach SP2 button in the Value field of the Parameter tab. The measurement value at that time will be automatically set to SSC.1 Param.SP1 or SSC.1 Param.SP2, and the result of Teach Result State will be SP1 Success or SP2 Success.

E = + + + I direct write mode				
mmon Process Data Identification Observation Parameter Diagnosis Scope Ga	eneric IO	DD		
ame	R/W	 Value	State	Unit
-] General Settings				
System Command	wo	Application Reset		
- ] Device Parameterisation				-
User Variable UInt8_1	rw	0	d	
User Variable UInt8_2	rw	0	d	
User Variable UInt8_3	rw	User Variable UInt8_3 Enumeration Value 0	• d	
User Variable UInt8_4	rw	User Variable UInt8_4 Enumeration Value 0	• d	
User Variable UInt16_1	rw	0	d	
User Variable UInt16_2	rw	0	d	-
User Variable UInt16_3	rw	0	d	
User Variable UInt16_4	rw	0	d	
User Variable UInt32_1	rw	0	d	
User Variable UInt32_2	rw	0	d	
User Variable UInt32_3	rw	0	d	-
User Variable UInt32_4	rw	0	d	
-] Switching Signal Channel 1				
SSC.1 Param.SP1	rw	52540	d	
SSC.1 Param.SP2	rw	40000	d	
SSC.1 Config.Logic	rw	High active	• d	
SSC.1 Config.Mode	rw	Two point	• d	
SSC.1 Config.Hyst	rw	0	d	
-] Switching Signal Channel 2				
SSC.2 Param.SP1	rw	0	d	
SSC.2 Param.SP2	rw	0	d	
SSC.2 Config.Logic	rw	High active	• d	
SSC.2 Config.Mode Press Teach SP1	rw	Deactivated	• d	
SSC.2 Config.Hyst	rw	0	d	
-] Teach				
Teach Select	rw	Default Channel	• d	
[-] Teach - Single Value				
System Command Successful Teach-in	wo	Teach SP1	d	
Successium reach-in	wo	Teach SP2		
Teach Result State	ro	SP1 success	d	

Figure 54. IO-Link Device Tool V5.1 – PE (SetPoint Settings by Device Measurement Value)

Note: Teach Select is not supported in this sample application. Do not change it.



## 6.6.7.5 Read Parameters

The user can click the Upload from device button to read the current parameters written to the device. For details about the Upload from device button, refer to section, 6.6 EK-RA2E1 Board Sensor Demo of IO-Link Device Tool.

#### 6.6.7.6 Reset Parameters to Default Values

Reset the device settings to default values.

1. Click the **Application Reset** button.

RA2E1 Starterkit @ IO-Link-Master02-USB (COM6)[0, 4]				
E ≥ + ↑ ↑ block write mode				
Common Process Data Identification Observation Parameter Diagnosis Scope Ge	neric IC	DD		
Name	R/W	Value	State	Unit
[-] General Settings				
System Command	wo	Application Reset		
[-] Device Parameterisation				
User Variable UInt8_1	rw	0	i	
User Variable UInt8_2	rw	0	i	

#### Figure 55. IO-Link Device Tool V5.1 – PE (Application Reset)

Note: When Application Reset is performed, the operation mode is set to the default, Deactivated, and LED2/LED3 are always off. To change the operation mode, refer to section, 6.6.7.3 Change Operation mode for operation.



## 6.6.8 IODD Tab

This tab displays the IODD information.

■  ] + + +   block iommon Process Data Identific		Parameter Diagnosis Scope Generic IODD
Data Sheet Process Data Vari	ables XML	
IODD TMG-RA2E1-Star	terkit-20210715-IODD	1.1×ml
Version V1.1 Relea	se Date 2021	-07-15 Copyright Copyright 2021, TMG Technologie und Engineering GmbH Stamp 286709888
	Vendor Name	TMG TE GmbH
🚷 IO-Link	Vendor Text	TMG TE GmbH Technologie Management Gruppe
	Vendor URL	http://www.tmgte.com Technologie und Engineerin
	Vendor ID	335 0×014F
	Device Family	Starterkit
	Device Name	RA2E1 Starterkit
	Device ID	266257 0x041011 Product ID RA2E1-01
IO-Link Revision	1.1	Data Storage X Profile Characteristics
compatible with V1.0	X	Block Parameterization X Common Profile
Bitrate	COM2	Device Access Locks
MinCycleTime	6.4 ms	Local User Interface
SIO mode		Local Parameterization
Process Data In/Out	6/0 Bytes	
RA2E1-01		
Name RA2E1 Starter	sit	Connection Type M12_4ConnectionT
Description ID-Link Starte	rkit with RA2E1 Proce	ssor
		2 3 4 M1224

Figure 56. IO-Link Device Tool V5.1 – PE (IODD tab)



## 7. Examples of Use

This chapter describes an example of a sample application.

The measurement data (Measurement Value) and the switching state during operation are transferred from the IO-Link device to the IO-Link master and PC via IO-Link communication. Open the Process Data tab and Scope tab of the IO-Link Device Tool, and check the changes in the values in subsequent operations.

## 7.1 Reset IO-Link parameters to default values

Reset the IO-Link parameters of EK-RA2E1 before starting operation, according to section, 6.6.7.6 Reset Parameters to Default Values.

## 7.2 Operating Methods

This chapter shows an example of operation with the setting values shown below.

Action Mode	Window
SP1	55,000
SP2	45,000
ZSSC resolution	16 bit

The operation steps are as follows:

- 1. Set the operating mode to Window according to section, 6.6.7.3 Change Operation mode.
- 2. Turn the SRB dial counterclockwise to set the lowest limit.

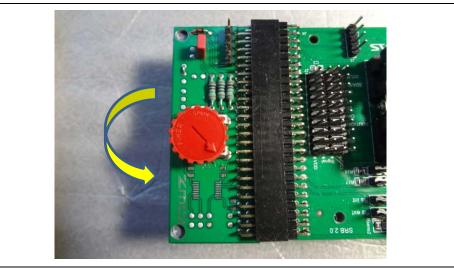


Figure 57. SRB Lower Limit Setting



LED2 is off because the measurements are less than SP2.

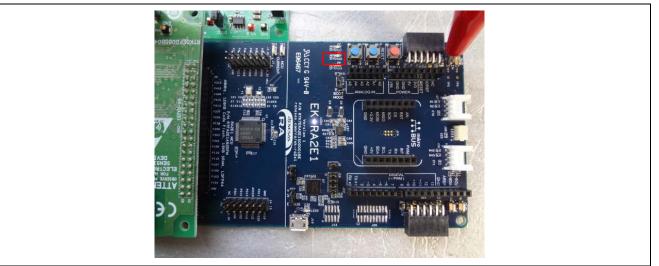


Figure 58. LED Status - Less than SP2

3. Turn the SRB dial clockwise.

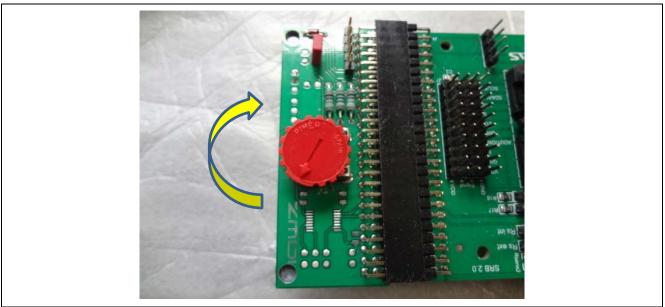


Figure 59. SRB - SP2 Location

LED2 lights up when the measured value is SP2 or higher. The position of the dial at this time is shown in Figure 60.



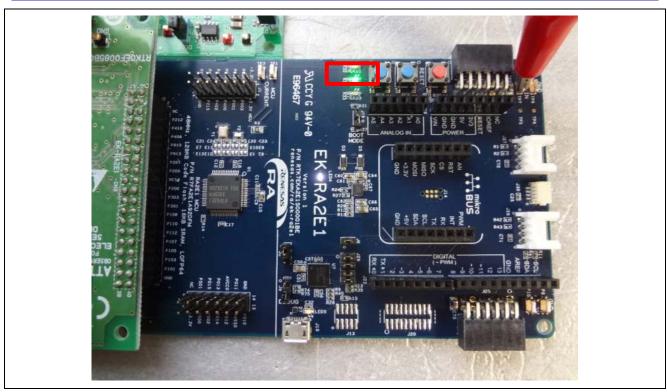


Figure 60. LED Status - SP2 or Higher

4. Turn the SRB dial further clockwise.

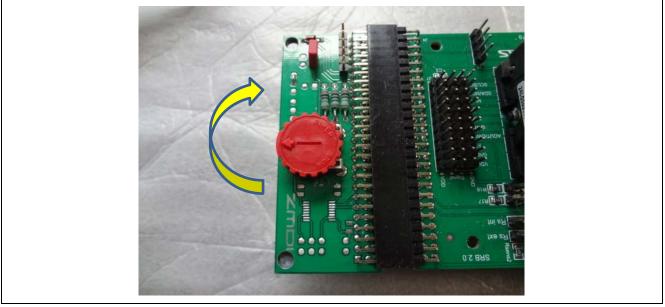


Figure 61. SRB - SP1 Reached

When the measured value exceeds SP1, the LED switches to LED3 (red). The position of the dial at this time is shown in Figure 62.



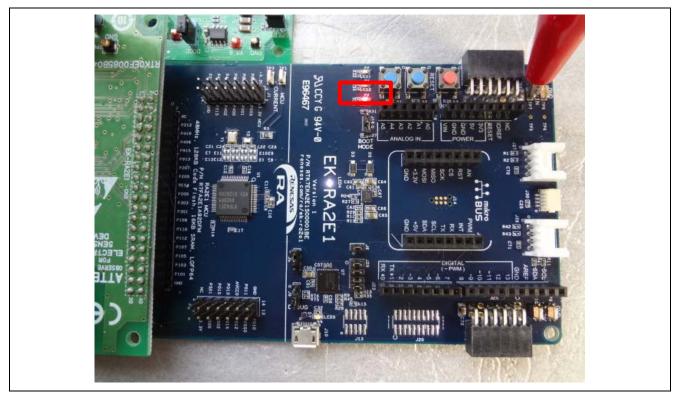


Figure 62. LED Status - SP1 Excess

- Note: Measurement with ZSSC is performed with the AA<sub>HEX</sub> command, which is one of the Measurement Commands of ZSSC. For the AA<sub>HEX</sub> command, refer to the following materials. - <u>ZSSC3240 Evaluation Kit User Manual</u> (Table 9. Measurement Commands)
  - ZSSC3240 DataSheet (Table 33. Command List)



## 8. How to Change ZSSC Settings

ZSSC settings are made from the ZSSC GUI on the PC while the Windows PC is connected to the EK-RA2E1 board with a USB-SERIAL conversion cable.

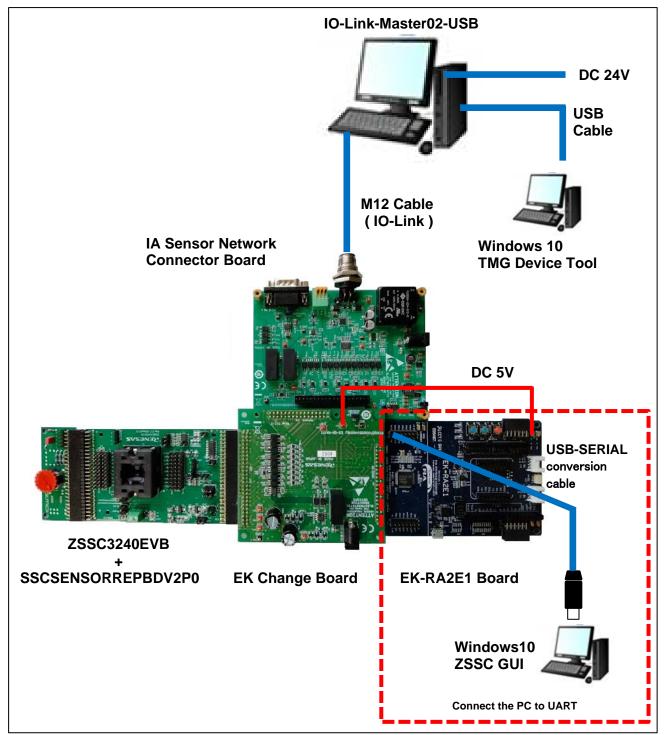


Figure 63. USB-SERIAL Conversion Cable Connection Status



## 8.1 USB-SERIAL Conversion Cable Connection

Since EK board does not have USB interface for communication with PC, it connects USB-SERIAL conversion cable to J1-9 (P401), J1-10 (P402) and J1-14 (GND) of the J1 connector to realize communication with PC by virtual COM.

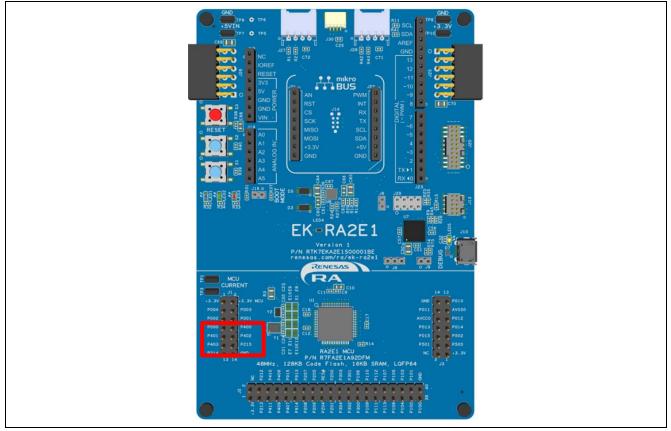


Figure 64. EK-RA2E1 Board J1 Connector

Connect the RXD/TXD/GND lines of the USB-SERIAL conversion cable with built-in FT232RL as follows.

Any cable with built-in features equivalent to FT232RL can be used.

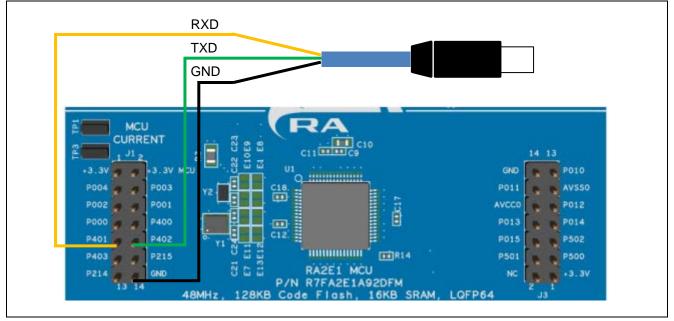


Figure 65. Connecting the USB-SERIAL Conversion Cable



## 8.2 Check the Virtual COM Port Number

When connecting USB-SERIAL converter cable to PC, the driver is automatically selected and recognized as a COM port.<sup>note1</sup>

Check the virtual COM port number of the USB-SERIAL converter cable in Device Manager of Windows.<sup>note2</sup>

The following is an example when recognized as COM7.

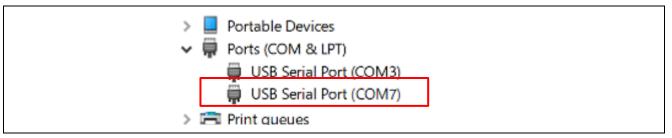


Figure 66. Device Manager

- Note 1. When using FT232RL compatible cables, some drivers may not be set automatically. In that case, get the driver and set the driver manually.
  - 2. The name displayed may be different depending on the USB-SERIAL conversion cable used.



## 8.3 Start the ZSSC GUI

Start the ZSSC GUI. The following graphic shows the ZSSC GUI screen after startup.

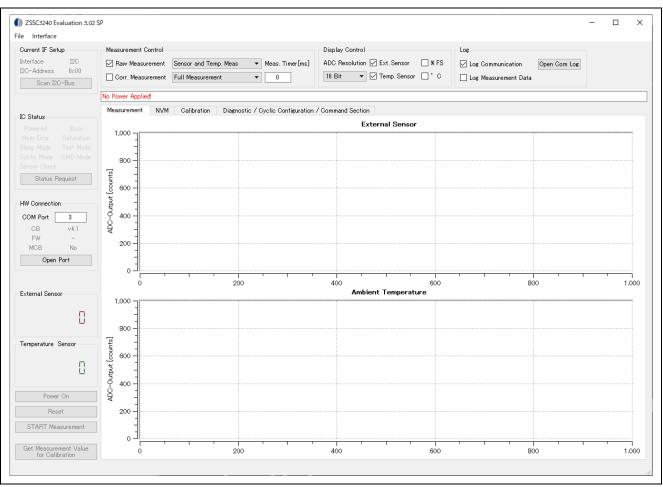


Figure 67. Screen after Starting ZSSC GUI

Note: The GUI is displayed after about 10 seconds of communication negotiation.

Note: Communication negotiation is performed by COM Port default COM3 in the GUI, and an error message is displayed if communication cannot be confirmed.

Mes	ssage Box		×
	Communication ease Check Conne		nd!
		OK	

Figure 68. Communication Error Display at GUI Startup



## 8.4 Establish a Communication Path

## 8.4.1 Open Port

For **COM Port**, set the COM port number checked in Figure 66, and click the **Open Port** button.

Current IF Setup	Measurement Control
Interface I2C I2C-Address 0x00 Scan I2C-Bus	Raw Measurement     Sensor and Temp. Meas     Meas. Timer[ms]     ADC Resolutio       Corr. Measurement     Full Measurement     0     16 Bit
	No Power Applied
IC Status Powered Busy Mem Error Saturation	Measurement NVM Calibration Diagnostic / Cyclic Configuration / Command Secti 1,000
Status Request	
COM Port 7 CB v4.1	

#### Figure 69. Open Port

Note: If the COM port used is COM3, **Open Port** is automatically selected.

If the Open Port is successful, the GUI screen changes as shown in Figure 70.

Current IF Setup	Measurement Control
Interface I2C I2C-Address 0x00 Scan I2C-Bus	Raw Measurement     Sensor and Temp. Meas     Meas. Timer[ms]     ADC Resolution       Corr. Measurement     Full Measurement     0     16 Bit
	No Power Applied!
IC Status Powered Busy	Measurement NVM Calibration Diagnostic / Cyclic Configuration / Command Section
	800 -
Sensor Check Status Request	
HW Connection	prteint [
COM Port 7 CB V4.1 FW V4.19	

#### Figure 70. Open Port Success

Note: If communication with the default COM3 is successful and Open Port is automatically selected, the IC Status and other displays may differ from the example shown in Figure 70.



## 8.4.2 Interface

Select Interface > I2C. note1

Gu 🗸 12C	Measurement Cont	rol		Display Control
Inte SPI D	🖂 Raw Measurem	ent Sensor and Temp. Mea	as 🔹 Meas. Timer[ms]	ADC Resolution
12C OWI 00	🗌 Corr. Measuren	Full Measurement	• 0	16 Bit 🔻 🗸
Setup	No Power Applied!			
IC Status	Measurement	NVM Calibration Diag	gnostic / Cyclic Configuration	/ Command Section
Powered Busy	1 000			Ext
	1,000			
	800 -			
	_			
Sensor Check	_			
Sensor Check	_			
Sensor Check Status Request	_			
Sensor Check Status Request HW Connection	utput [counts]			

Figure 71. Interface Selection

Confirm that I2C [400kHz] is displayed in the Interface of Current IF Setup. note2

ZSSC3240 Evaluation 3.02 SI	þ		
File Interface			
Current IF Setup Interface I2C [400kHz] I2C-Address 0x0 Scan I2C-Bus	Measurement Control	<ul> <li>Meas. Timer[ms]</li> <li>0</li> </ul>	Display Control ADC Resolution ☑ 16 Bit ▼ ☑

Figure 72. Current IF Setup Interface

- Note 1. This sample application operates on I2C only; SPI and OWI cannot be used.
  - 2. If the Interface display does not change to **I2C [400 kHz]** as shown in Figure 72, select **I2C** from the **Interface** menu again.



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## 8.4.3 Scan I2C-Bus

Click Scan I2C-Bus button to detect ZSSC I2C devices.

Current IF Setup	Measurement Control Display Control
Interface I2C [400kHz]	Raw Measurement Sensor and Temp. Meas  Meas. Timer[ms] ADC Resolution
I2C-Address 0x0 Scan I2C-Bus	Corr. Measurement Full Measurement
	No Power Applied!
IC Status	Measurement NVM Calibration Diagnostic / Cyclic Configuration / Command Section
	1,000
	_
	800 -
	000 T
Sensor Check	
Sensor Check	
Sensor Check Status Request	
Sensor Check Status Request HW Connection	

#### Figure 73. Scan I2C-Bus

When I2C device is detected, the message shown in Figure 74 appears. Communication with the ZSSC3240 is now possible.

Comment IE Setur	Measurement Control
Current IF Setup	Measurement Control Display Control
Interface I2C [400kHz]	Raw Measurement Sensor and Temp. Meas  Meas. Timer[ms] ADC Resolution
I2C-Address 0x0 Scan I2C-Bus	Corr. Measurement
	Valid I2C-address found:0x0!
IC Status	Measurement NVM Calibration Diagnostic / Cyclic Configuration / Command Section
Powered         Busy           Mem Error         Saturation           Sleep Mode         Test Mode           Oyclic Mode         CMD Mode           Sensor Check         Status Request	
HW Connection COM Port 7 CB V4.1 FW V4.19 MCB No Close Port	Pontant 2000

Figure 74. I2C Device Detection



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## 8.5 Measurement (Corr. Measurement)

This chapter provides an example of a measurement using the ZSSC GUI tool based on the setting values shown in the table below.

Action Mode	Two Point
SP1	55,000
SP2	45,000
ZSSC resolution	16bit

Note: Each graph image was captured separately for illustration purposes after [Start Measurement]. They are not based on continuous measurements.

The steps to make a measurement are as follows:

- 1. Set the operating mode to Two point according to section, 6.6.7.3 Change Operation mode.
- 2. Check Corr. Measurement and select Full Measurement. If Temp. Sensor is checked, uncheck it.

Current IF Setup	Measurement C	Control Display Control
Interface I2C [400kHz]	Raw Measu	urement Sensor and Temp. Meas. 👻 Meas. Timer[ms] ADC Resolution 🗹 Ext. Sensor
I2C-Address 0x0		
Scan I2C-Bus	Corr. Measu	urement Full Measurement 0 16 Bit 🔻 🗌 Temp. Senso
	Measurement	NVM Calibration Diagnostic / Cyclic Configuration / Command Section
IC Status		External Sense
IC Status Powered Busy	1.000	External Senso
	1,000	External Senso
Powered Busy	1,000 ]	External Senso
<b>Powered</b> Busy Mem Error Saturation	1,000 -	External Senso

Figure 75. Corr. Measurement

3. Turn the SRB dial counterclockwise to set it to the lowest limit.

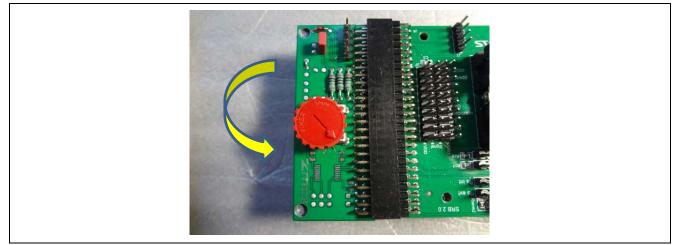


Figure 76. SRB Lower Limit Setting

#### 4. Start measurement

Click **START Measurement** to start measurement with the sensor connected to the ZSSC3240EVB and begin graph display. After the click operation, the button changes to the **STOP Measurement** display.



**Examples of IO-Link Solutions** 

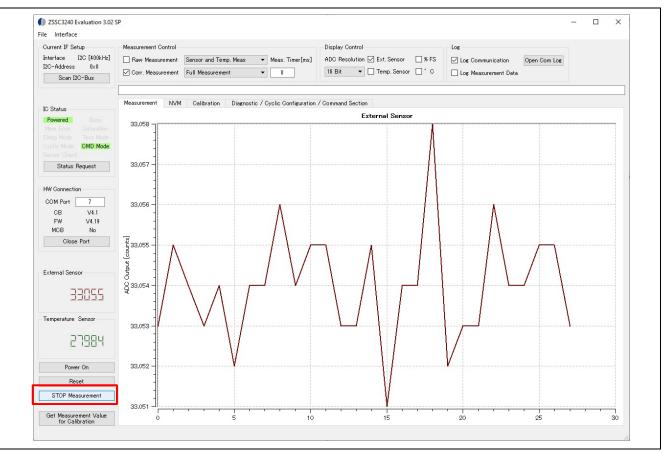


Figure 77. Start Measurement

Note: The graph scale is automatically adjusted according to the measured values. When the dial is not operated immediately after the start of measurement, there is little change in the measurements, so the scale is displayed with a grid unit of 1.



#### 5. Turn the SRB dial clockwise until the External Sensor value is just before SP1 (55000).

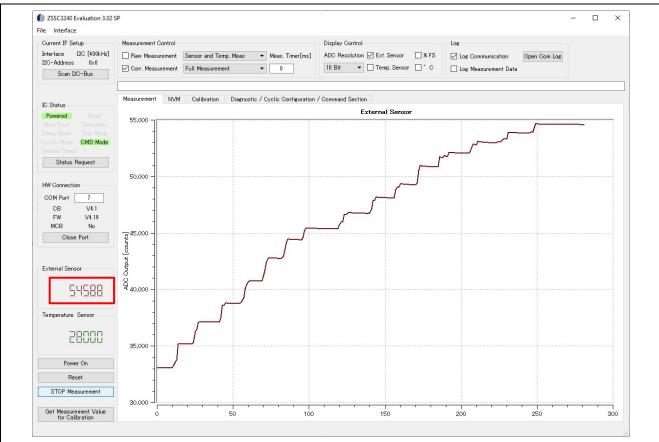


Figure 78. Measurement - SP1 Front

LED2 is off because the measured value is SP1 or less.

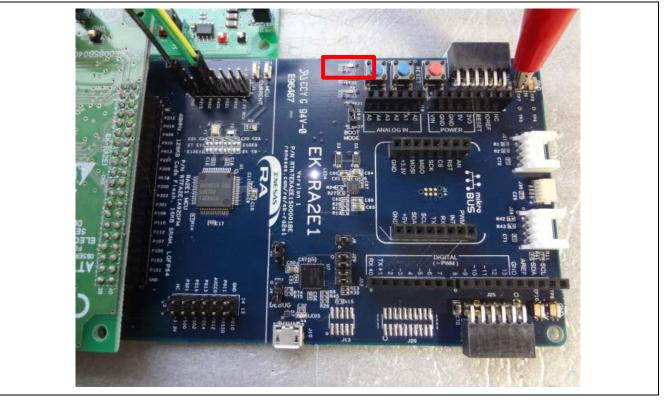


Figure 79. LED Status - SP1 or Less



6. Turn the SRB dial clockwise until the External Sensor value exceeds SP1 (55000).

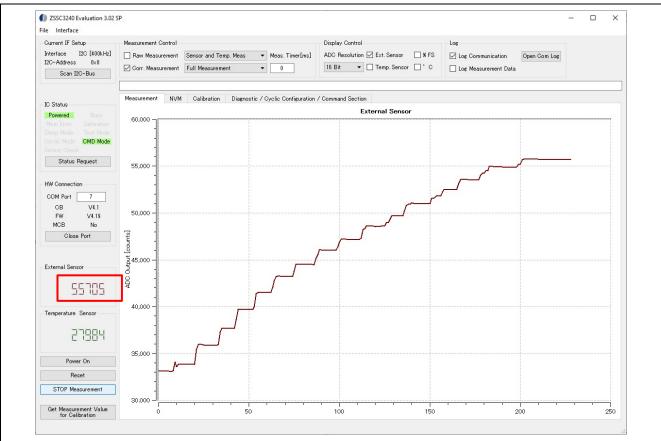


Figure 80. Measurement - SP1 Excess

LED2 lights up when the measured value exceeds SP1.

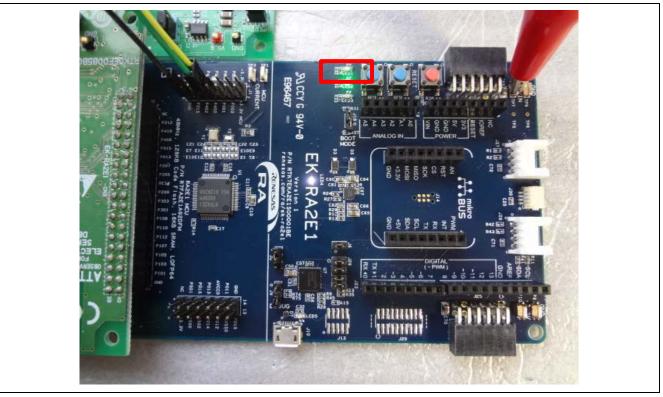


Figure 81. LED Status - SP1 Excess



#### 7. Turn the SRB dial counterclockwise until the External Sensor value is less than SP2 (45000).

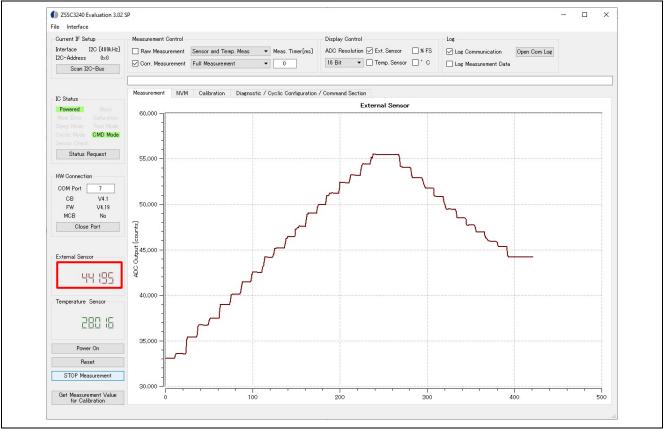


Figure 82. Measurement – Less than SP2

LED2 will turn off when the measured value less than SP2.

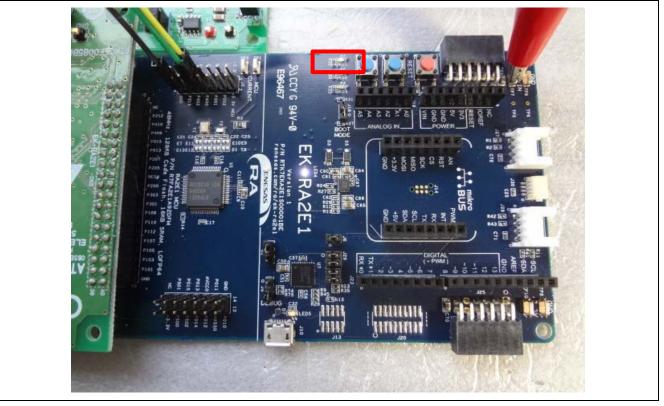


Figure 83. LED Status - Less than SP2



## 8.6 NVM Operation

This section explains how to operate the NVM (non-volatile memory) registers in the ZSSC.

## 8.6.1 Read NVM

Select the **NVM** tab. Initially, no values are loaded.

File Interface										
Current IF Setup	Measu	rement Control			Display Control		Log			
Interface I2C [400kHz]	Ras	w Measurement Sensor and T	Temp. Meas 🔻 Mea	s. Timer[ms]	ADC Resolution 🗹 Ext	. Sensor 📃 🕷 FS	🗹 Log C	ommunication Open	Com Log	
I2C-Address 0x0	Cor	r. Measurement Full Measure	ment 👻	0	16 Bit 🔻 🗌 Ten	mp. Sensor 🔲 * C		leasurement Data		
Scan I2C-Bus	_									
IC Status	Measu	remen NVM Calibration	n Diagnostic / Cyclic	Configuration /						
Powered Busy		Name	Value (nex)	^	SM Config 1/2			Ext. Temp. Config 1/2		
	00	Customer_ID_0	0000							
Sleep Mode Test Mode Cyclic Mode CMD Mode	01	Customer_ID_1	0000		Gain	1.32	-	Gain	1.82	-
Sensor Check	02	Interface Config	0000		Polarity	Positive	•	Polarity	Positive	-
Status Request	03	Smart Sensor F. I/O 1	0000		ADC Resolutio	n 12 Bit	•	ADC Resolution	12 Bit	-
	04	Smart Sensor F. I/O 2	0000		ADC Offset	0%	-	ADC Offset	0%	•
HW Connection	05	OFFSET_S	0000		ADC Reference	e Bandgap	•	ADC Reference	Bandgap	-
COM Port 7	06	GAIN_S	0000		IN-Offset	0mV (no shift)	•	IN-Offset	0mV (no shift)	-
CB V4.1 FW V4.19	07	TCG	0000		T bias out	5uA	-	T bias out	5uA	•
MCB No	08	тсо	0000		ADC Gain/Offs	et Off	•	ADC Gain/Offset	Off	•
Close Port	09	SOT_TCO	0000		CM Adjustmen	nt Off	•	GM Adjustment	Off	-
	0A	SOT_TCG	0000							
External Sensor	OB	SOT_SENS	0000		Smart Sensor Funct	tion 1/0_1		Smart Sensor Function	1/0.2	
External Jensor	oc	OFFSET_T	0000					DAC resolution 13B		•
П	0D	GAIN_T	0000		Default Mode C	Command Mode	•			-
<u> </u>	OE	SOT_T	0000		OWI Listen Time 5	Oms	-			-
Temperature Sensor	OF	OFFSET_S / GAIN_S	0000		OWI SU Case S	itartup Window	-			•
	10	TCG/TCO	0000		Temp. Source in	nternal PTAT	•			•
0	11	SOT_TCO / SOT_TCG	0000		Sensor Supply R	latiometric Supply VDDI	з 👻			•
	12	SOT_SENS / OFFSET_T	0000		Internal Rt 1.	.3kOhm	•	LDOctri On		•
Power On	13	GAIN_T / SOT_T	0000		External Rt N	lo -	-	LDOctrl Voltage VDD	= 4.8)/	-
Reset	14	SM_CONFIG 1	0000		OWI off O	WI enabled	•			•
START Measurement	15	SM_CONFIG 2	0000		NVM lock N	IVM write OK	•			•
		-		*	Charge Pump O	'n	•	Oversampling No (		•
Get Measurement Value for Calibration		Write NVM	Read NVM					oversumpting No c	/1018.	

Figure 84. NVM Tab Initial State

Click **Read NVM** to communicate with ZSSC and read the values.



File Interface								
Current IF Setup	Measurement Control		Display Control		Log			
Interface I2C [400kHz] I2C-Address 0x0	Raw Measurement Sensor an	nd Temp. Meas 🔹 Meas. Timer[ms]	ADC Resolution 🗹 Ext. Sen:	sor 🗌 % FS	🗹 Log Commun	ication Open	Com Log	
Scan I2C-Bus	Corr. Measurement Full Meas	urement 👻 🛛	16 Bit 🔻 🗌 Temp. Se	ensor 🗌 * C	Log Measure	ment Data		
IC Status	Measurement NVM Calibra	tion Diagnostic / Cyclic Configuratio						
Powered Busy	Name	Value [hex]	SM Config 1/2		Ext	Temp. Config 1/2		
	00 Customer_ID_0	0000						
Cyclic Mode CMD Mode	01 Customer_ID_1	0000	Gain	48	•	Gain	1.32	•
	02 Interface Config	0000	Polarity	Positive	•	Polarity	Positive	•
Status Request	03 Smart Sensor F. I/O 1	0000	ADC Resolution	16 Bit	-	ADC Resolution	16 Bit	-
	04 Smart Sensor F. I/O 2	0824	ADC Offset	0%	-	ADC Offset	0%	-
HW Connection	05 OFFSET_S	0000	ADC Reference	Ratiometric	•	ADC Reference	Bandgap	-
COM Port 7	06 GAIN_S	0000	IN-Offset	0mV (no shift)	•	IN-Offset	0mV (no shift)	•
CB V4.1 FW V4.19	07 TCG	0000	T bias out	5uA	-	T bias out	5uA	-
MCB No	08 TCO	0000	ADC Gain/Offset	Off	-	ADC Gain/Offset	Off	-
Close Port	09 SOT_TCO	0000	CM Adjustment	On	•	CM Adjustment	Off	-
	0A SOT_TCG	0000						
External Sensor	OB SOT_SENS	0000	Smart Sensor Function D	01	Smi	art Sensor Function	I/O 2	
External control	OC OFFSET_T	0000			DA	C resolution 13Bit		-
П	0D GAIN_T	0000		and Mode	•	Dithering Dithe	ring Off	-
-	OE SOT_T	0000	OWI Listen Time 50ms		•	AC Input Sens	or -> DAC	•
Temperature Sensor	OF OFFSET_S / GAIN_S	0020	OWI SU Case Startup	o Window	<b>ب</b>	nalog Out DAC	Output	•
_	10 TCG/TCO	0000	Temp. Source interna	I PTAT	-		/DD ratiom/R2R	-
0	11 SOT_TCO / SOT_TCG	0000	Sensor Supply Ration	etric Supply VDDB	-	iagnotstic Anali	e Diaenostic Off	-
	12 SOT_SENS / OFFSET_T	0000	Internal Rt 1.3kOh	m	-	LDOctrl On		-
Power On	13 GAIN_T / SOT_T	2000	External Rt No		-	octri Voltage VDD	= 5.2V	-
Reset	14 SM_CONFIG 1	8417	OWI off OWI en	abled	<b>•</b>		Sensor Off	•
START Measurement	15 SM_CONFIG 2	0200	NVM lock NVM v	rite OK	-		Temp. Off	-
		~	Charge Pump On		-	ersampling No O		•
Get Measurement Value for Calibration	Write NVM	Read NVM			0,	No C		•

Figure 85. Read NVM Tab State after Execution



## 8.6.2 Write NVM

Change the setting value and execute Write NVM to transfer the setting to ZSSC. The following is an example of changing the ADC resolution.

Select 24-bit for **ADC Resolution** in **SM Config 1/2**. The changes are highlighted with a red background in the register list, as shown in Figure 86. ADC Resolution Change

<ul> <li>ZSSC3240 Evaluation 3.02</li> <li>File Interface</li> </ul>	SP							-		
Current IF Setup		rement Control		Display Control						
Interface I2C [400kHz] I2C-Address 0x0 Scan I2C-Bus	🗌 Ras		d Temp. Meas   Meas. Timer[ms] urement  0	ADC Resolution 🗹	Ext. Sensor 🗍 % FS Temp. Sensor 🗋 * C		iommunication	Open Com Log		
IC Status	Measu	urement NVM Calibrat	tion Diagnostic / Cyclic Configuration	/ Command Section						
Powered Busy Mem Error Saturation	00	Name Customer_ID_0	Value [hex]	SM Config 1/2			Ext. Temp. Config	1/2		
Sleep Mode Test Mode	01	Customer_ID_1	0000	Gain	48	-	Gain	1.82	-	
Cyclic Mode CMD Mode Sensor Check	02	Interface Config	0000	Polarit	Positive	-	Polarity	Positive	-	
Status Request	03	Smart Sensor F. I/O 1	0000	ADC Resol	ution 24 Bit	-	ADC Resolut	ion 16 Bit		
	04	Smart Sensor F. I/O 2	0824	ADC Off	set ON	•	ADC Offse	t OK	-	
HW Connection	05	OFFSET_S	0000	ADC Refer	ence Ratiometric	-	ADC Referen	Bandgap	-	
COM Port 7 CB V4.1 FW V4.19	06	GAIN_S	0000	IN-Offs	et 0mV (no shift	• •	IN-Offset	0mV (no shift	• (	
	07	TCG	0000	T bias o	ut 5uA	•	T bias out	5uA	-	
MCB No	08	TCO	0000	ADC Gain/	Offset Off	•	ADC Gain/Of	fset Off	-	
Close Port	09	SOT_TCO	0000	CM Adjust	On	•	CM Adjustm	ent Off	•	
	0A	SOT_TCG	0000							
External Sensor	08	SOT_SENS	0000	Smart Sensor Fe	Smart Sensor Function 1/0 1			Smart Sensor Function I/O 2		
	oc	OFFSET_T	0000	Defects Mede	Command Mode	-	DAC resolution	13Bit	•	
0	OD	GAIN_T	0000	OWI Listen Time			Dithering	Dithering Off	•	
	OE	SOT_T	0000		Startup Window	-	DAC Input	Sensor -> DAC	-	
Temperature Sensor	OF	OFFSET_S / GAIN_S	0020	Temp. Source	internal PTAT		Analog Out	DAC Output	-	
0	10	TCG / TCO	0000	Sensor Supply		DB T	Aout Setup	Ext. VDD ratiom/R2R	•	
U.	11	SOT_TCO / SOT_TCG	0000	Internal Rt	1.3kOhm	•		Analog Diagnostic Off	-	
Power On	12	SOT_SENS / OFFSET_T	0000	External Rt	No	•		On	-	
Reset	13	GAIN_T / SOT_T	2000	OWI off	OWI enabled	-	LDOctrl Voltage		-	
START Measurement	14	SM_CONFIG 1	8C17	NVM lock	NVM write OK	•		AZM Sensor Off	•	
o FART Medaurement	13	SM_CONFIG 2	0200	Charge Pump	On	-		AZM Temp. Off	•	
Get Measurement Value for Calibration		Write NVM	Read NVM				Oversampling	No Overs.	-	

Figure 86. ADC Resolution Change

Click **Write NVM**. The changes are transferred to the NVM register of the ZSSC. When the transfer is complete, the red background of the highlighted changes will turn off.

ZSSC3240 Evaluation 3.02 File Interface										- 0	×
		12.0.2					10				
Current IF Setup Interface I2C [400kHz]		rement Control		Display Control			Log	_			
Interface I2C [400kH2] I2C-Address 8x8		w Measurement Sensor and Ti		ADC Resolution			Log Co	Log Communication Open Com Log			
Scan I2C-Bus	Ø ¢¢	rr. Measurement Full Measurem	nent 💌 0	16 Bit 👻 🗌 🤇	Temp. Se	msor □°C	Log M	leasurement Data			
10 Chata	Meas	rement NVM Calibration	Diagnostic / Cyclic Configuration	/ Command Section							
IC Status Powered Busy		Name	Value [hex]	SM Config 1/2				Ext. Temp. Config 1/2			
Mem Error Saturation	00	Customer_ID_0	0000								
Sleep Mode Test Mode Oyclic Mode CMD Mode	01	Customer_ID_1	0000	Gain		48	-	Gain		1.32	-
Sensor Check	02	Interface Config	0000	Polarity		Positive	-	Polarity		Positive	-
Status Request	03	Smart Sensor F. I/O 1	0000	ADC Resolution	rtion	24 Bit	•	ADC Resolut	tion	16 Bit	-
	04	Smart Sensor F. I/O 2	0824	ADC Offs	et	0%	-	ADC Offse	et	0%	-
HW Connection	05	OFFSET_S	0000	ADC Refere	nce	Ratiometric	-	ADC Referen	nce	Bandgap	•
COM Port 7	06	GAIN_S	0000	IN-Offse	t	0mV (no shift)	-	IN-Offset		0mV (no shift)	-
CB V4.1 FW V4.19	07	TCG	0000	T bias or	at	5uA	-	T bias out	t	5uA	•
MCB No	08	TCO	0000	ADC Gain/C	ffset	Off	-	ADC Gain/Of	ffset	Off	-
Close Port	09	SOT_TCO	0000	CM Adjustr	nent	On	•	CM Adjustm	ent	Off	•
	0A	SOT_TCG	0000								
External Sensor	OB	SOT_SENS	0000	Smart Sensor Fu	nction I/	01		Smart Sensor Fur	nction I/	0 2	
External Jensor	oc	OFFSET_T	0000		Command Mode			DAC resolution			-
П	OD		0000	Default Mode			-				-
-	OE	SOT_T	0000	OWI Listen Time	50ms		-		Sensor		-
Temperature Sensor	OF	OFFSET_S / GAIN_S	0020	OWI SU Case			•		DAC OU		•
_	10	TCG / TCO	0000	Temp. Source			•	and a second		D ratiom/R2R	-
0	11	SOT_TCO / SOT_TCG	0000	Sensor Supply		etric Supply VDDB	•			Diagnostic Off	-
	12	SOT_SENS / OFFSET_T	0000	Internal Rt	1.3kOh	m	•		On		•
Power On	13	GAIN_T / SOT_T	2000	External Rt	No		•	LDOctrl Voltage		5.2V	-
Reset	14	SM_CONFIG 1	8C17	OWI off	OWI en	abled	•			nsor Off	
START Measurement	15	SM_CONFIG 2	0200	NVM lock	NVM w	rite OK	•		AZM Te		-
			~	Charge Pump	On		•		No Over		•
Get Measurement Value for Calibration		Write NVM	Read NVM								

Figure 87. Write NVM



Note: If **Write NVM** is executed without having read the settings by **Read NVM**, the existing values may be unintentionally overwritten. Be sure to read the existing settings with **Read NVM** before executing **Write NVM**.

Click Reset to reset the ZSSC EVB. This operation reflects the NVM settings to the system.

Current IF Setup	Meas	urement Control			Display Control		Log					
Interface I2C [400kHz]	R	aw Measurement Sensor and T	emp. Meas 🔻 Meas. Tir	ner[ms]	ADC Resolution 🗹 E	xt. Sensor 🗌 % FS	Log C	Communication Open Com Log				
I2C-Address 0x0 Scan I2C-Bus	Ø	orr. Measurement Full Measurem	nent 👻 0	]	16 Bit 💌 🗌 T	emp. Sensor 🔲 * C	Log M	easurement Data				
IC Status	Meas	urement NVM Calibration	Diagnostic / Cyclic Cont	liguration	/ Command Section							
Powered Busy		Name	Value [hex]	•	SM Config 1/2			Ext. Temp. Config 1/2				
Mem Error Saturation		Customer_ID_0	0000									
Sleep Mode Test Mode Cyclic Mode CMD Mode	01	Customer_ID_1	0000		Gain	48	-	Gain	1.82		-	
Sensor Check	02	Interface Config	0000		Polarity	Positive	-	Polarity	Positive		-	
Status Request	03	Smart Sensor F. I/O 1	0000		ADC Resolut	tion 24 Bit	-	ADC Resolut	tion 16 Bit		-	
	04	Smart Sensor F. I/O 2	0824		ADC Offse	0%	-	ADC Offse	et 0%		-	
HW Connection	05	OFFSET_S	0000		ADC Referen	Ratiometric	-	ADC Referen	nce Bandgap		•	
COM Port 7 CB V4.1 FW V4.19	06	GAIN_S	0000		IN-Offset	0mV (no shift)	•	IN-Offset	0mV (no	shift)	-	
	07	TCG	0000		T bias out	5uA	-	T bias out	5uA		-	
MCB No	08	тсо	0000		ADC Gain/Of	fset Off	-	ADC Gain/Of	fset Off		•	
Close Port	09	SOT_TCO	0000		CM Adjustm	ent On	•	CM Adjustm	ent Off		-	
	0A	SOT_TCG	0000									
External Sensor	OB	SOT_SENS	0000		Smart Sensor Fun	ction I/O 1		Smart Sensor Fur	nction I/O 2			
	OC	OFFSET_T	0000		2 2 Percent			DAC resolution	13Bit		-	
0	0D	GAIN_T	0000			Command Mode	•	Dithering	Dithering Off		-	
	OE	SOT_T	0000		OWI Listen Time		•	DAC Input	Sensor -> DAC		-	
Temperature Sensor	OF	OFFSET_S / GAIN_S	0020		OWI SU Case		•	Analog Out	DAC Output		•	
	10	TCG/TCO	0000			internal PTAT	-	Aout Setup	Ext. VDD ratiom/	R2R	-	
0	11	SOT_TCO / SOT_TCG	0000			Ratiometric Supply VDD		Diagnotatic	Analog Diagnostic	Off	-	
	12	SOT_SENS / OFFSET_T	0000			1.3kOhm	-	LDOctrl	On		•	
Power On	13	GAIN_T / SOT_T	2000			No	-	LDOctrl Voltage	VDD = 5.2V		-	
Reset	14	SM_CONFIG 1	8C17			OWI enabled	•	AZ Sensor	AZM Sensor Off		-	
START Measurement	15	SM_CONFIG 2	0200			NVM write OK	•	AZ Temp.	AZM Temp. Off		-	
Get Measurement Value for Calibration		Write NVM	Read NVM		Charge Pump	On	•	Oversampling	No Overs.		•	

Figure 88. Reset

Note: The **Write NVM** execution alone does not make the setting effective. Be sure to reset the ZSSC EVB with the **Reset** button.

## 8.6.3 Write CRC

If CheckSum is inconsistent due to NVM change, the IC Status Mem Error lights up after the **Reset** button operation.

File Interface											
Current IF Setup Interface I2C [400kHz] I2C-Address 0x0 Scan I2C-Bus		nt Control asurement Sensor and asurement Full Measur			Display Control ADC Resolution ☑ Ext. Sensor			Los Open Com Los Open Com Los Los Measurement Data			
	Measuremen	nt NVM Calibrati	on Diagnostic / Cyclic (	Configuration	/ Command Section						
Powered Busy Mam Error Saturation	00	Name Customer_ID_0	Value [hex]	^	SM Config 1/2			- Ext. Temp. Confi	e 1/2		
Sleep Mode Test Mode	01	Customer_ID_1	0000		Gain	48	•	Gain	1.82		-
Cyclic Mode CMD Mode Sensor Check		Interface Config	0000		Polarity	Positive	-	Polarity	/ Posi	tive	•
Status Request		nart Sensor F. I/O 1	0000		ADC Resol	ution 24 Bit	-	ADC Resolu	ution 16 E	ät	•
	04 Sm	nart Sensor F. I/O 2	0824		ADC Offs	et 0%	•	ADC Offs	set 0N		•
HW Connection	05	OFFSET_S	0000		ADC Refer	Ratiometric	-	ADC Refere	ence Band	ieap	-
COM Port 7	06	GAIN_S	0000		IN-Offs	nt 0mV (no shit	t) 🔻	IN-Offee	at 0mV	(no shift)	-
CB V4.1 FW V4.19	07	TCG	0000		T bias o	ut SuA	-	T bias or	ut 5uA		•
MCB No	08	тсо	0000		ADC Gain/0	Offset Off	-	ADC Gain/C	Offset Off		-
Close Port	09	SOT_TCO	0000		CM Adjust	nent On	•	CM Adjustr	ment Off		•
	OA	SOT_TCG	0000								
External Sensor	OB	SOT_SENS	0000		Smart Sensor Fu	nction 1/0 1		Smart Sensor Fu	unction I/O 2		
	oc	OFFSET_T	0000					DAC resolution	13Bit		
0	OD	GAIN_T	0000			Command Mode	-	Dithering	Dithering Off		-
~	OE	SOT_T	0000		OWI Listen Time		-	DAC Input	Sensor -> DA	0	
Temperature Sensor	OF O	OFFSET_S / GAIN_S	0020		OWI SU Case	Startup Window	-	Analog Out	DAC Output		
	10	TCG / TCO	0000		Temp. Source	internal PTAT	•	Aout Setup	Ext. VDD ratio	m/R2R	
0	11 SC	DT_TCO / SOT_TCG	0000		Sensor Supply	Ratiometric Supply VD	DB 👻	Diagnotatic	Analog Diagno	istic Off	
	12 50	T_SENS / OFFSET_T	0000		Internal Rt	1.3kOhm	•	LDOctrl	On		
Power On	13	GAIN_T / SOT_T	2000		External Rt	No	-	LDOctrl Voltage	VDD = 5.2V		-
Reset	14	SM_CONFIG 1	8C17		OWI off	OWI enabled	-	AZ Sensor	AZM Sensor C	Off	-
START Measurement	15	SM_CONFIG 2	0200	~	NVM lock	NVM write OK	•	AZ Temp.	AZM Temp. Of	ff	
Get Measurement Value for Calibration		Write NVM	Read NVM		Charge Pump	Un	•	Oversampling	No Overs.		٠

Figure 89. Mem Error



In this case, select the **Diagnostic / Cycle Configuration / Command Section** tab and click **Write CRC** to recalculate CheckSum and write it to NVM. If CheckSum is successfully reconfigured by NVM in ZSSC, MemError will turn off after the **Reset** button is clicked.

File Interface		
Current IF Setup	Measurement Control Display C	ontrol
Interface I2C [400kHz]	Raw Measurement Sensor and Temp. Meas  Meas. Timer[ms] ADC Res	olution 🗹 Ext. Sensor 🗌 🕷 FS 🛛 🗹 Log Communication 🛛 Open Com Log
I2C-Address 0x0 Scan I2C-Bus	Corr. Measurement	Temp.Sensor     C     Log Measurement Data
	Measurement NVM Calibration Diagnostic / Cyclic Configuration / Command	Section
IC Status	Cyclic Operation Sequence 1 / 2	DAC-Diagnostic On-Chip Diagnostics
Powered Busy		V DAC10 AOUT [V] = 0.52 INP □
	Sensor Bridge Meas. Enable  TM-Pause in Slots [0.63]	INN
Cyclic Mode CMD Mode	Temperature Meas. Enable V AZTM Duras in State	V_DAC90_AOUT [V] = 4.59 INP Range
Sensor Check	SC Check Disable - [0.68]	Set DAC-Input [0.65535] 0 INN Range
Status Request	SM in 1st Slot Enable - [0.15]	Apply DAC-Diagnostic Sensor Short
	170M Land Land Land AZCM Davies in Clate	T_EXT Open
HW Connection	[0.63]	T_EXT Range
COM Port 7	500-False in Solts 0	ADC-Diagnostic
CB V4.1 FW V4.19	A∠IM in 1st Slot Enable ▼	SSC Saturation
MCB No	SC Check in 1st Slot Enable - Opdate hate ons -	Set ADC-Input [0.31] 0 Memory Error
Close Port	Write to NVM	Die Crack
	INFITE TO INVINI	Apply ADC-Diagnostic
		Reset Diagnostic
External Sensor	Single Command Section	Output [hex]: 0 Apply Sensor Check
0	Start Command Mode	Output [hex]: 0
<u>u</u>		Terminal
Temperature Sensor	Start Sleep Mode	Write Commands:
remperatore densor		
0	Start Cyclic Mode	Send Write Command
	Single Measurement	Read Commands:
Perman On		
Reset	Wite ORS	Send Read Command
START Measurement	Apply HV-Supply(12V)	Output [hex]:
Get Measurement Value for Calibration		

Figure 90. Write CRC

## 8.6.4 Return ADC resolution set value

In section, 8.6.2 Write NVM the operation to change the ADC resolution to 24-bit was explained as an example of NVM change.

For section, 7.2 Operating Methods, return to 16-bit before the change. Follow the procedure below to set the ADC resolution to 16-bit.

- 1. Change the ADC resolution to 16-bit according to the procedure in section 8.6.2 Write NVM.
- 2. Correct and Reset MemError according to the procedure in section, 8.6.3 Write CRC.

## 9. References

- R11QS0035JGxxxx RA2E1 Group Evaluation Kit for RA2E1 MCU Group EK-RA2E1 Quick Start Guide
- R20UT4825JGxxxx RA2E1 Group Evaluation Kit for RA2E1 MCU Group EK-RA2E1 v1 User's Manual
- R01UH0852JJxxxx Renesas RA2E1 Group User's Manual: Hardware
- R11UM0155EU0270 Renesas Flexible Software Package (FSP) v3.7.0 User's Manual
- Renesas ZSSC3240 Evaluation Kit User Manual
- Renesas Datasheet ZSSC3240
- Renesas SSC Communication Board SSC-CB Datasheet



## **Revision History**

		Description			
Rev.	Date	Page	Summary		
1.00	Nov.01.22	-	First release		



# General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

#### 1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power is supplied until the power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable. Voltage application waveform at input pin

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a systemevaluation test for the given product.

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